



**The Medipix2 project: high-resolution
2-dimensional imaging using a hybrid pixel
detector in counting mode**

Michael Campbell

Ph Department

CERN

Geneva, Switzerland

Spokesman, Medipix2 Collaboration



The Medipix2 Consortium

- ◆ Institut de Fisca d'Altes Energies, Barcelona, Spain
- ◆ University of Cagliari and INFN Section thereof, Italy
- ◆ CEA, Paris, France
- ◆ CERN, Geneva, Switzerland,
- ◆ Universitat Freiburg, Freiburg, Germany,
- ◆ University of Glasgow, Scotland
- ◆ Universita' di Napoli and INFN Section thereof, Italy
- ◆ NIKHEF, Amsterdam, The Netherlands
- ◆ University of Pisa and INFN Section thereof, Italy
- ◆ University of Auvergne, Clermont Ferrand, France,
- ◆ Laboratory of Molecular Biology, Cambridge England
- ◆ Mitthogskolan, Sundsvall, Sweden,
- ◆ Czech Technical University, Prague, Czech Republic
- ◆ ESRF, Grenoble, France
- ◆ Academy of Sciences of the Czech Republic, Prague
- ◆ Universität Erlangen-Nurnberg, Erlangen, Germany
- ◆ University of California, Berkeley, USA

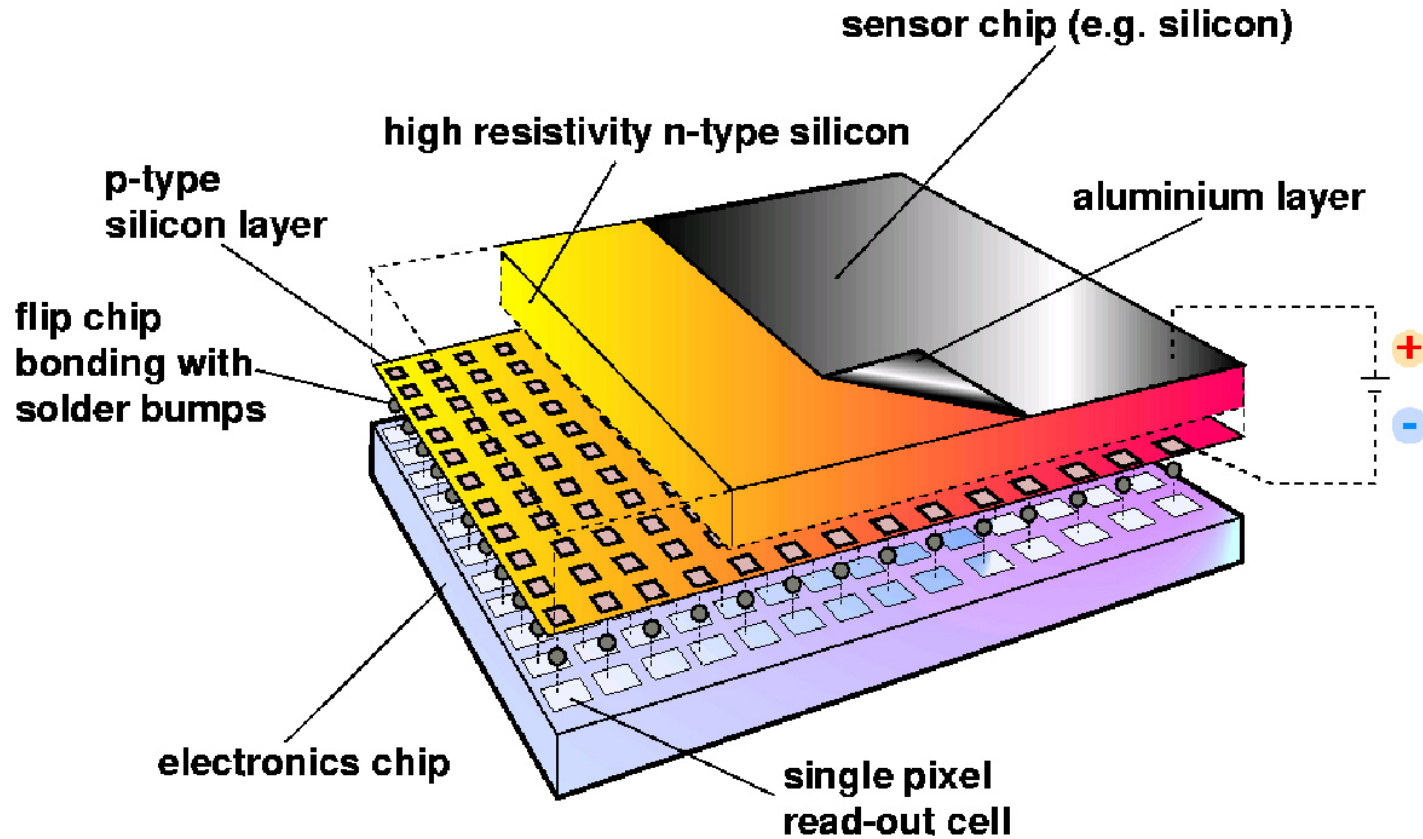


Outline

- ◆ **Introduction**
 - Origins of the hybrid pixel detector
 - Requirements for High Energy Physics (HEP)
 - Front-end electronics design considerations
 - From High Energy Physics to imaging
- ◆ **Progress in CMOS**
 - Moore's law
 - Implications for present and future designs
- ◆ **The Medipix2 System**
 - Chip design and electrical behaviour
 - Characterization of hybrid devices using radioactive sources and monochromatic x-ray beams
- ◆ **Applications**
 - X-ray imaging
 - Synchrotron (Pilatus)
 - Particle tracking
 - Neutron imaging
 - Electron microscopy
 - Adaptive optics for ground-based astronomy
- ◆ **Conclusions and Future Developments**



Hybrid Pixel Detector

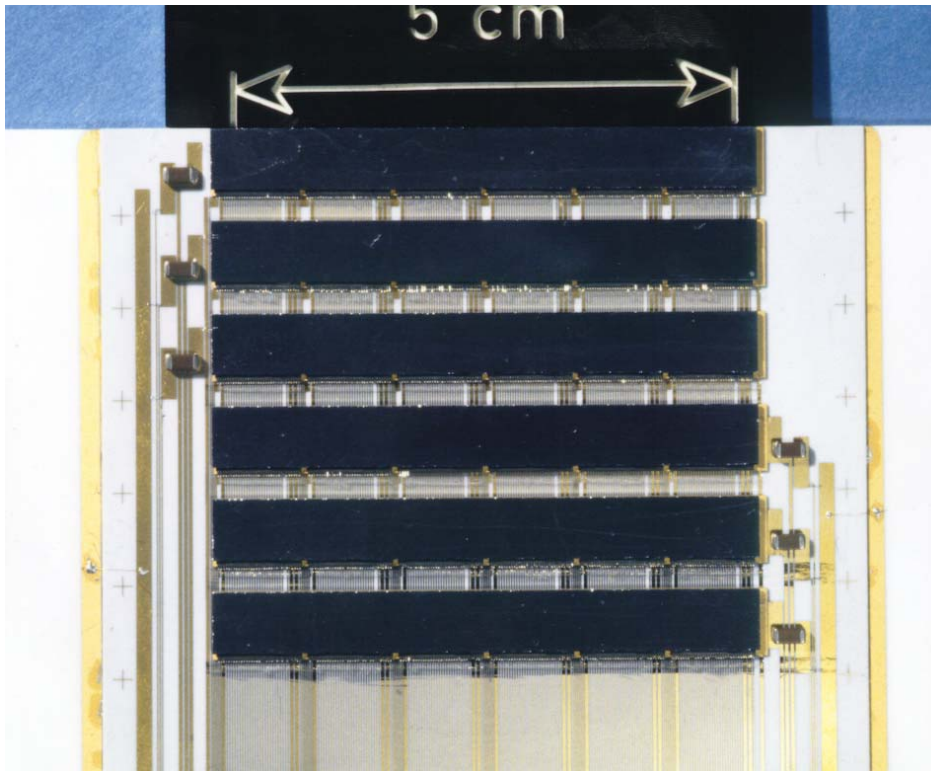


Detector and electronics readout are optimized separately

Hybrid Pixel Detector - Cross Section



The first large area pixel detector array



36 000 pixels

6 ladders of 6 chips

Each chip has 1000 pixels

2 arrays make up one logical plane

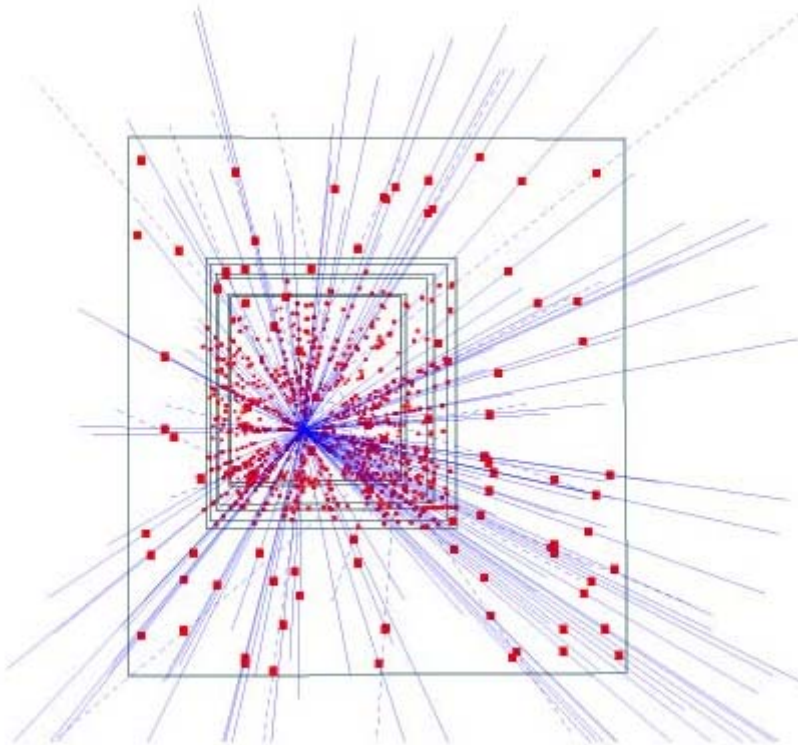
[E. Heijne, E. Chesi]

Work carried out by RD19 for WA97.

Basic development funded by CERN-LAA programme.



One Heavy Ion Physics Event



CERN Experiment WA97 (1995)

5 x 5 cm² area

7 detector planes

~ 0.5 M pixels

Pixel dimensions 75 x 500 μm²

Trigger precision 1 μsec

1 kHz trigger rate

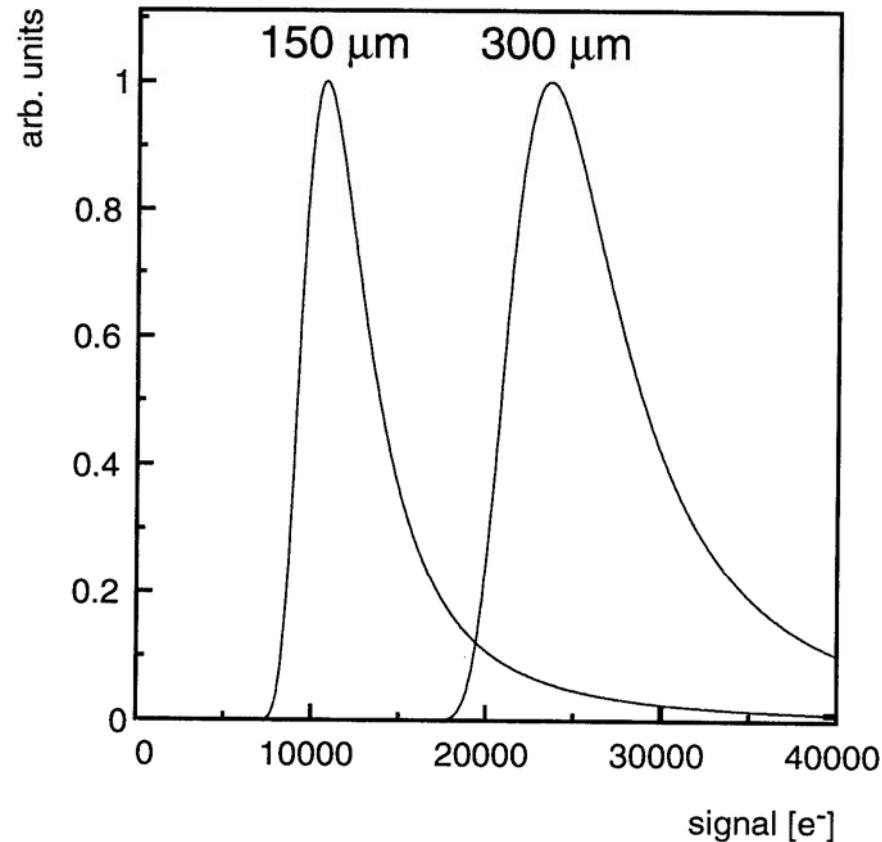


Implications of HEP requirements on front-end electronics design

- ◆ At LHC there will be 40M bunch crossing per second each generating around 1 000 tracks
- ◆ Therefore only 'interesting' events are read out and data must be stored until those events are selected
- ◆ Clean hit information must be provided to make tracking possible – 'pattern recognition'
- ◆ Tracking detectors therefore must tag events to single bunch crossings (high speed), provide clean hit information (low noise), consume little power (because of the cooling which would be required in a confined space) and tolerate high levels of radiation
- ◆ Pulse processing electronics must be used and event selection must take place on chip



Minimum Ionizing Charge Deposition in Si

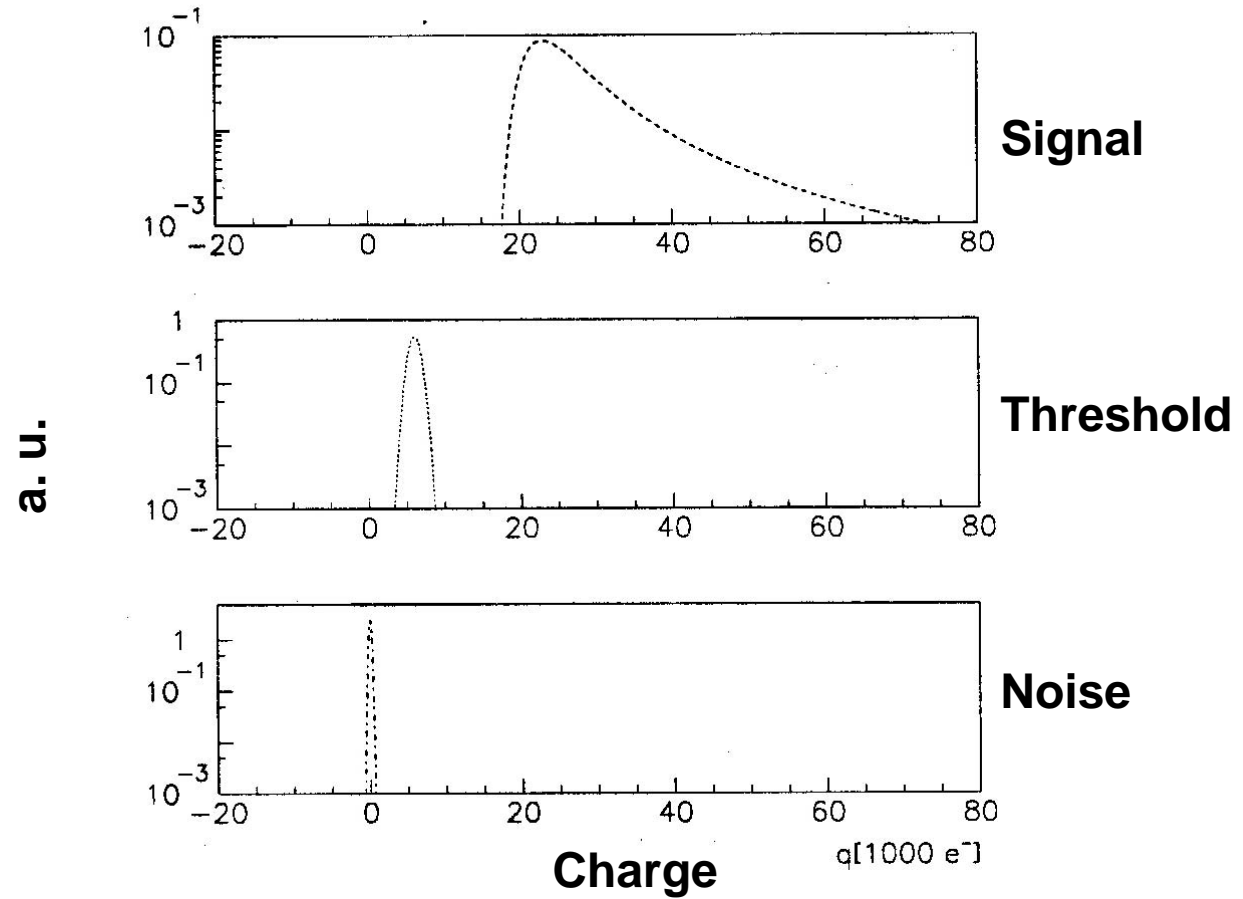


For 300μm thick detector most probable peak is 24 000 e⁻, roughly 60 keV

Because of charge sharing threshold normally set around 1/3rd Landau peak (4 - 8ke⁻)



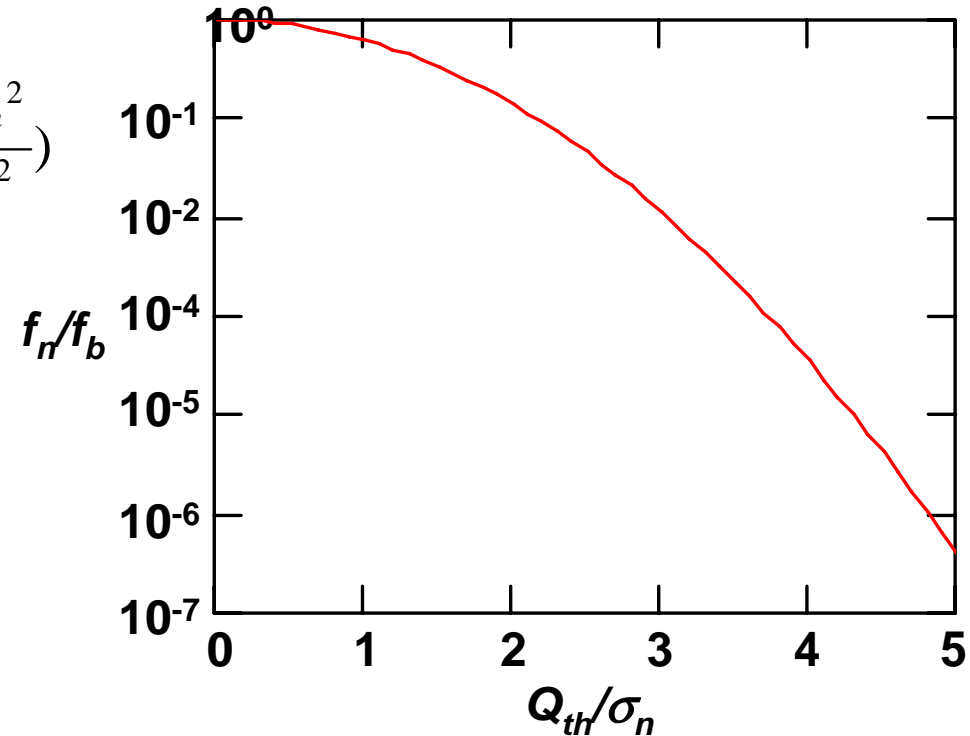
Signal, Threshold, Noise





Noise hit rate for a discriminator with bandwidth, f_b

$$f_n = \frac{1}{\sqrt{3}} f_b \exp\left(\frac{-Q_{th}^2}{2\sigma_n^2}\right)$$

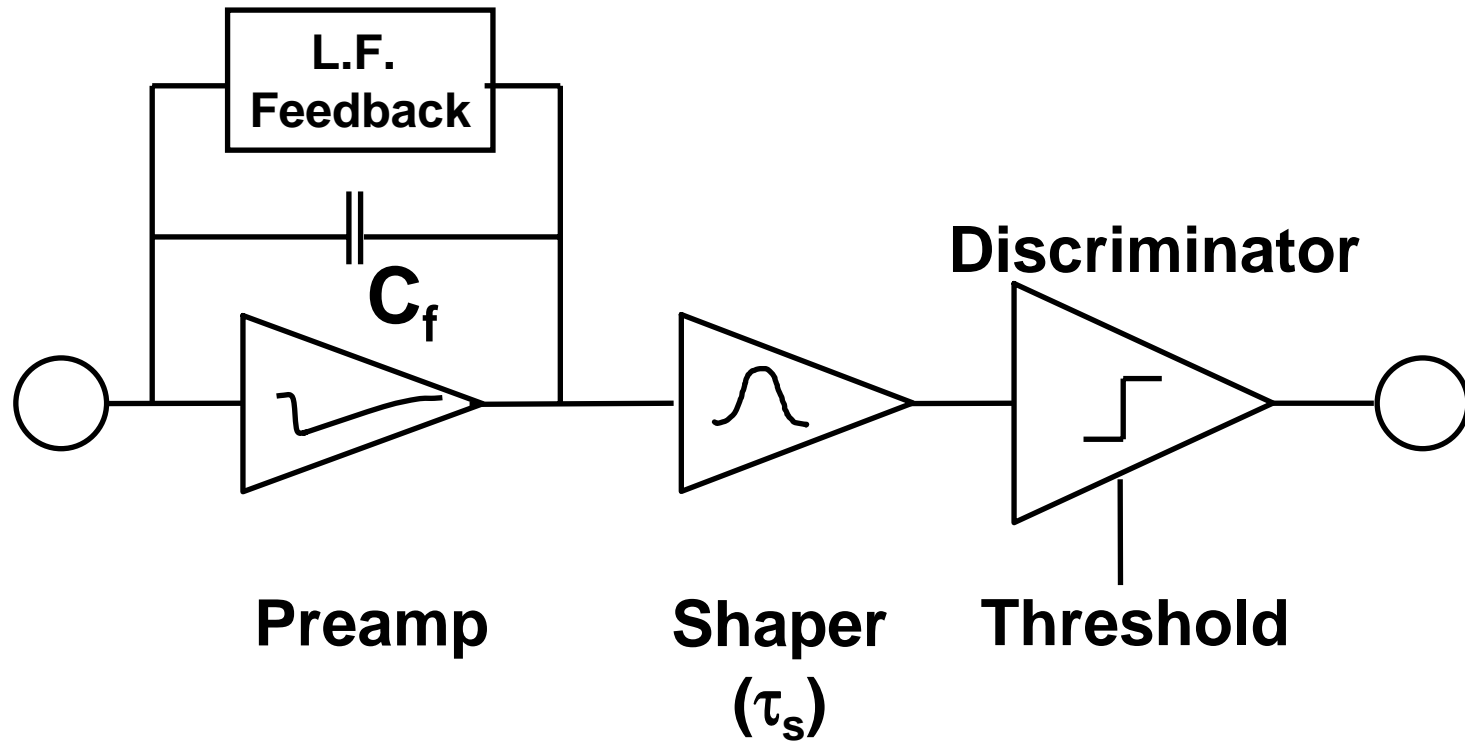


Q_{th} = threshold
 σ_n = noise

In a large bandwidth system (such as an HEP experiment) noise and threshold variation must be kept very far from the threshold to produce clean event information.



Typical front-end for HEP or single photon counting





Preamplifier noise and rise time

Series Noise:

$$ENC_d^2 \propto \frac{C_t^2}{g_m \tau_s}$$

Parallel noise:

$$ENC_o^2 \propto I_o \tau_s$$

Preamp rise time:

$$t_r \propto \frac{C_t (C_L + C_f)}{g_m C_f}$$

In general C_t should be minimized and g_m maximized, but more g_m means more power consumption.



Discrimination Threshold mismatch depends on transistor threshold mismatch..

$$\sigma^2(V_{th}) \propto \frac{A^2}{WL}$$

Transistor matching

**good matching requires large area transistors
but A is proportional to gate oxide thickness**

Therefore matching improves with technology shrinkage



From HEP to x-ray imaging

- ◆ **Pulse processing circuitry eliminates the effect of dark current noise from an image**
- ◆ **But readout should be changed from HEP (event stored until trigger arrival) to single photon counting (using a shutter)**
- ◆ **HEP pixels are small, but the wrong shape - usually rectangular for momentum measurements in magnetic fields**
- ◆ **All HEP applications use high ρ silicon because of uniformity and price. For x-ray imaging front-end circuits should allow both electron and hole collection to permit the use of exotic detector materials with high hole trapping**

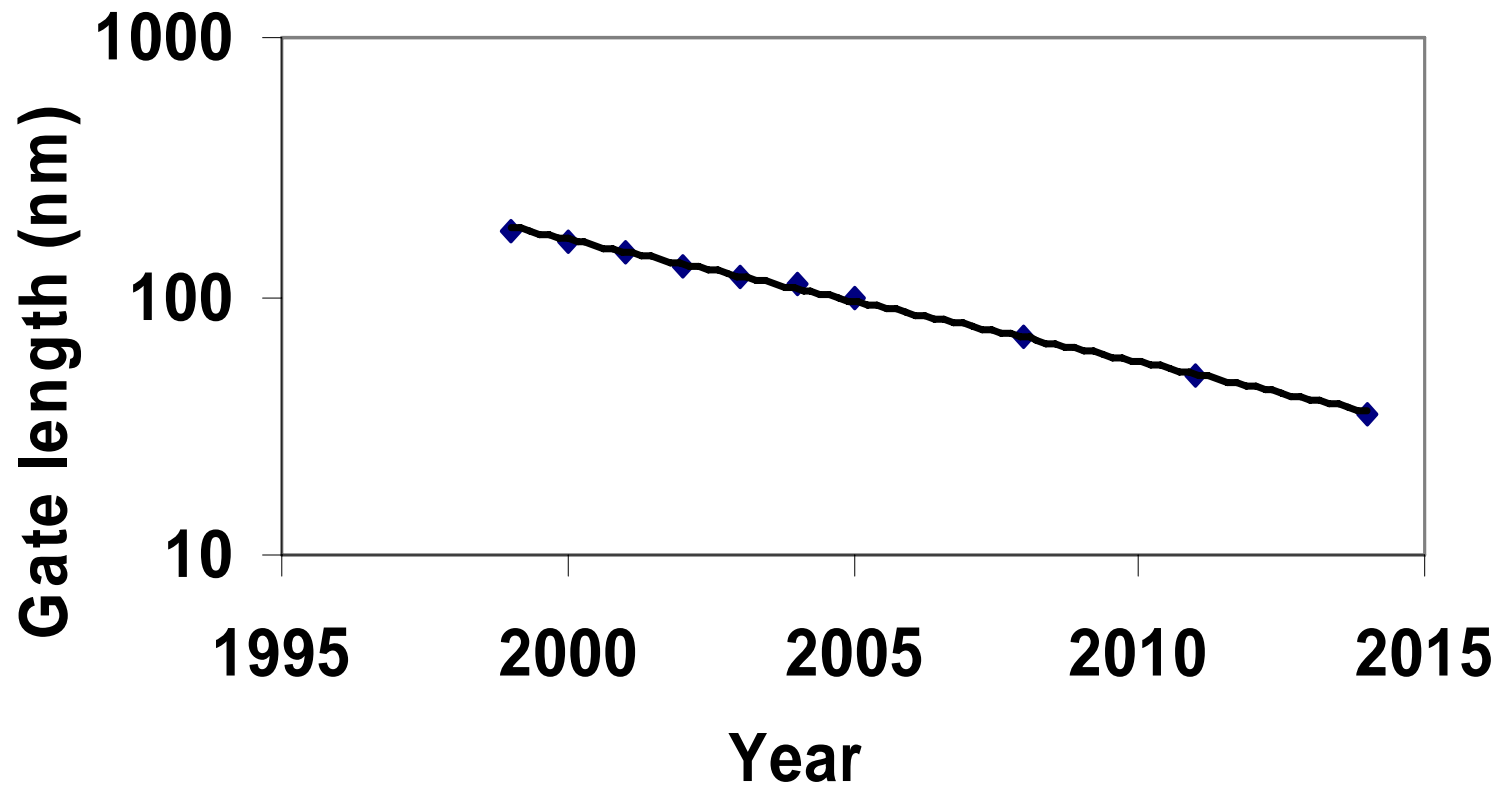


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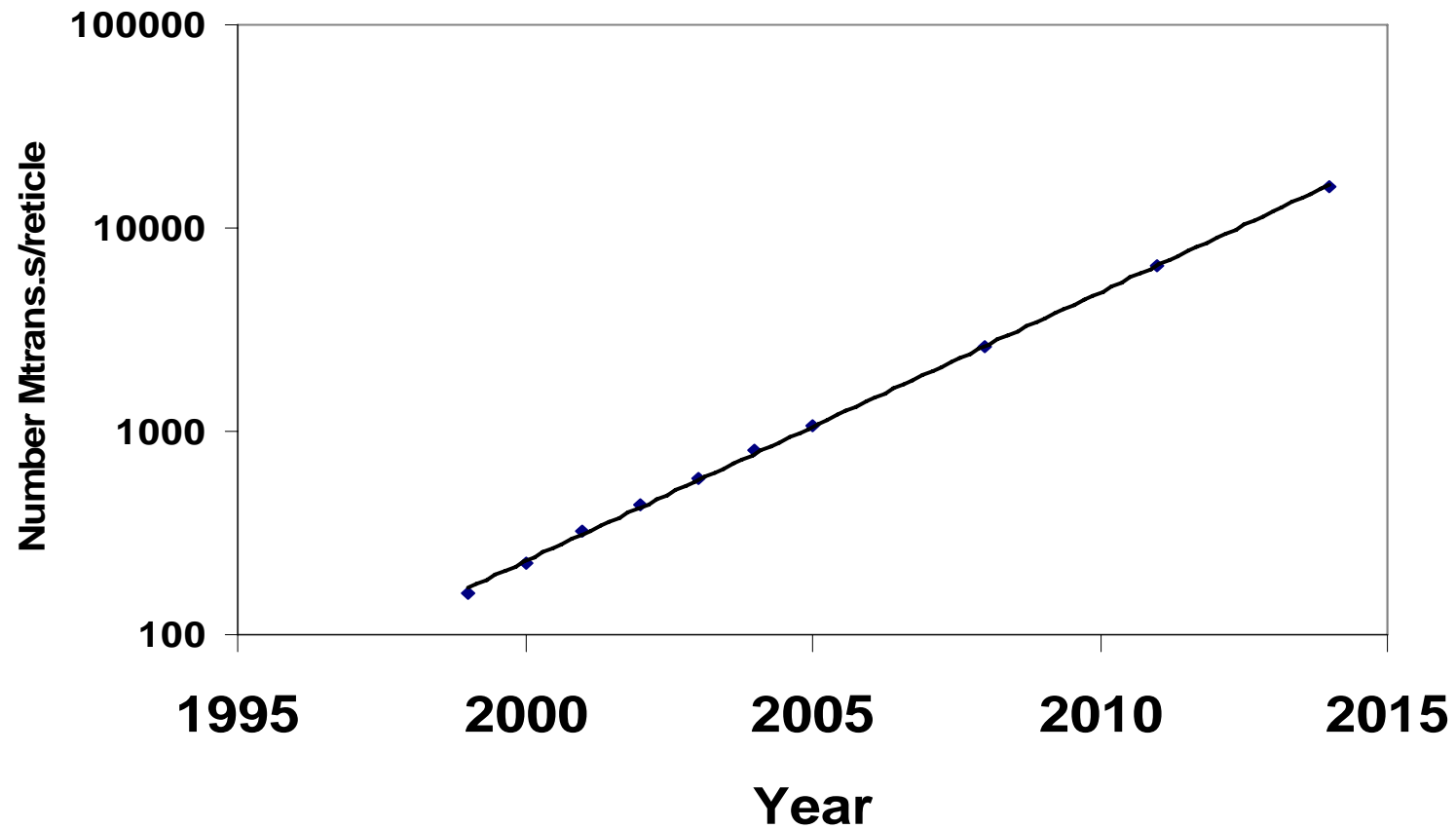
Moore's law - transistor feature size



SIA Roadmap 1999



Moore's Law - components per chip



SIA Roadmap 1999

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Implications of progress in CMOS processing for single photon counting

- ◆ **More and more functionality can be packed into a pixel**
- ◆ **Transistor matching for a fixed area and therefore pixel-to-pixel matching improves**
- ◆ **The cost/unit area of Si is more-or-less constant**
- ◆ **However, prototyping costs are increasing**
- ◆ **Power management becomes an issue**



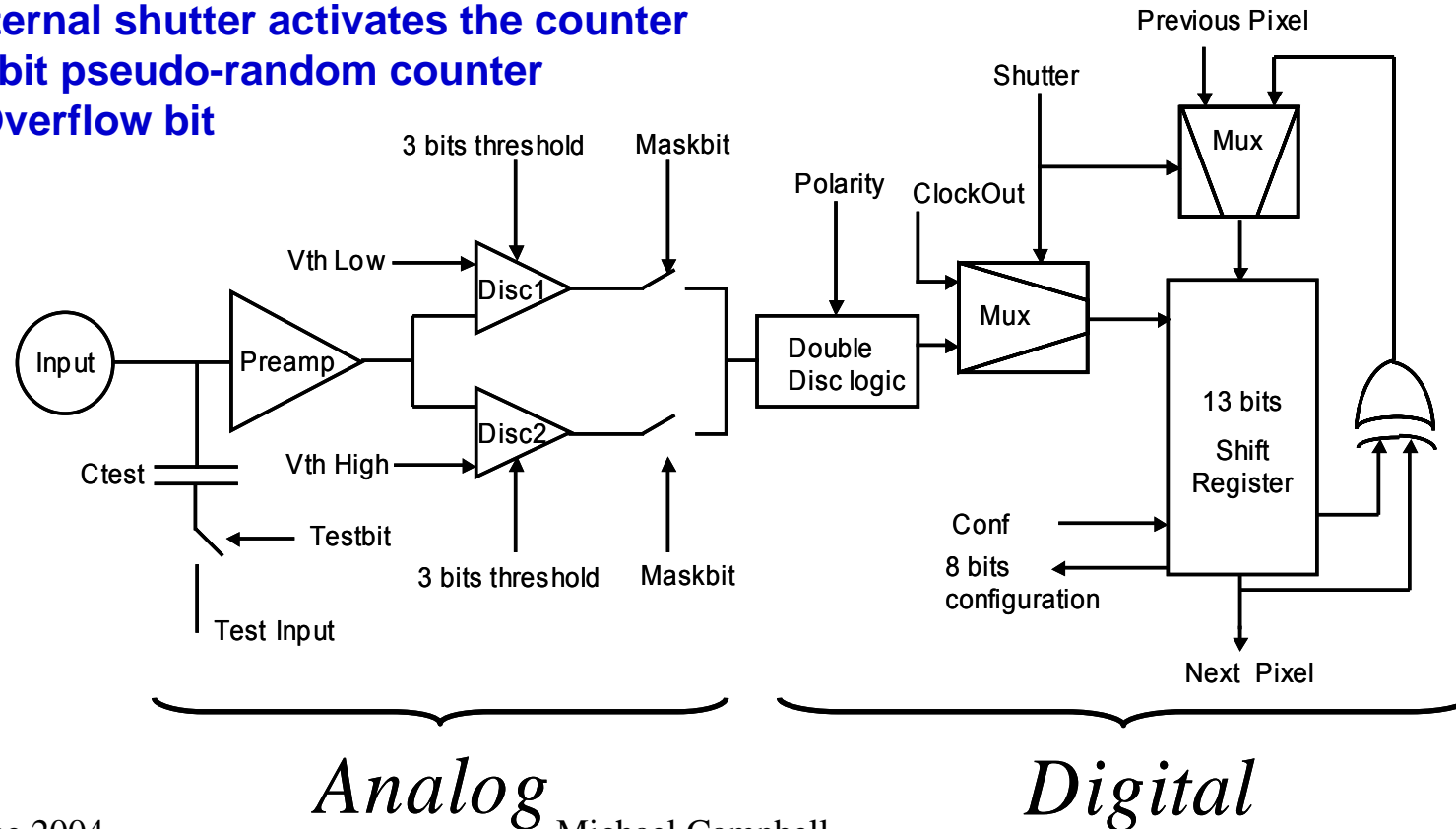
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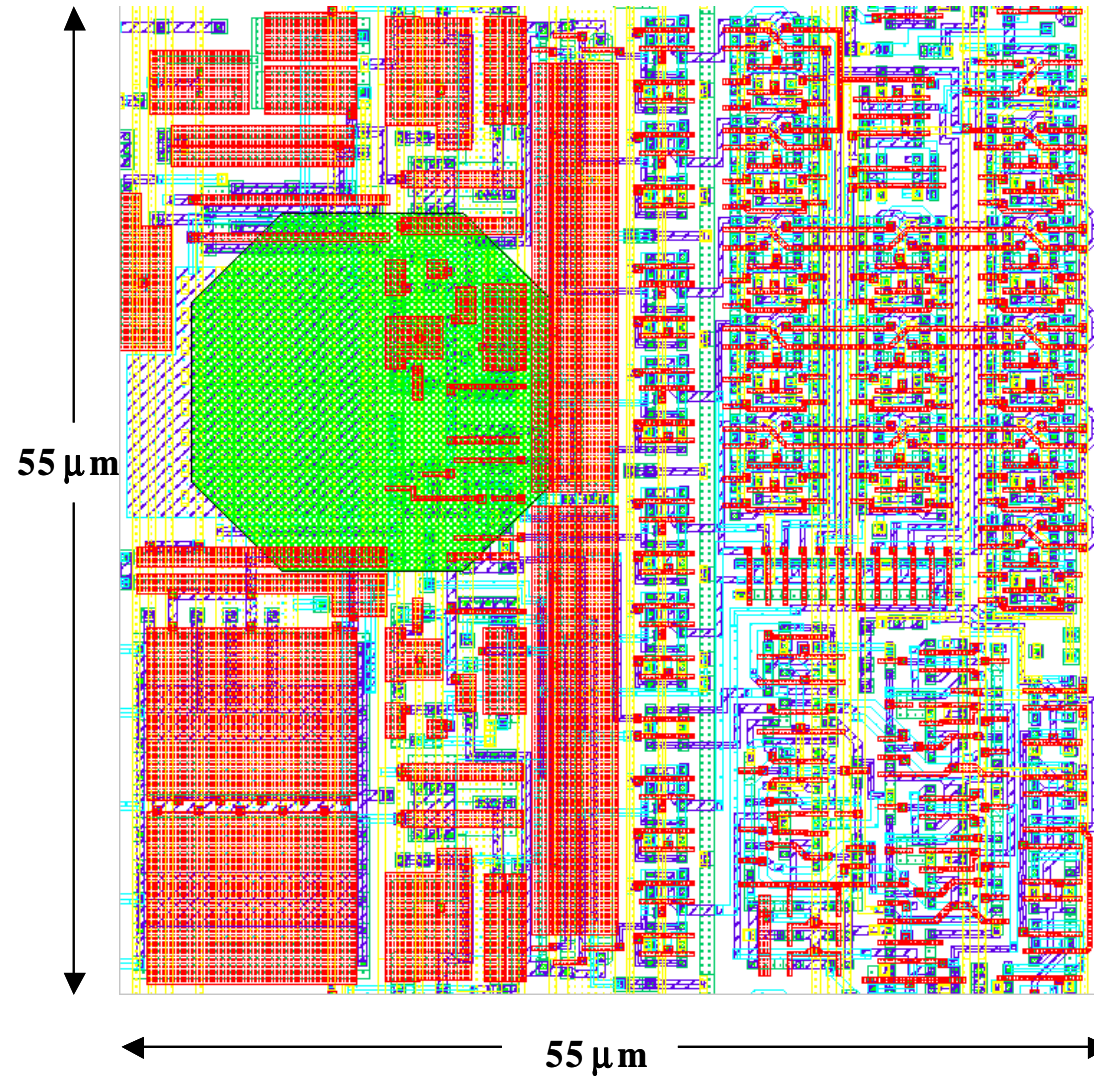
Medipix2 Cell Schematic

- Charge sensitive preamplifier with individual leakage current compensation
- 2 discriminators with globally adjustable threshold
- 3-bit local fine tuning of the threshold per discriminator
- 1 test and 1 mask bit
- External shutter activates the counter
- 13-bit pseudo-random counter
- 1 Overflow bit





Medipix2 Cell Layout



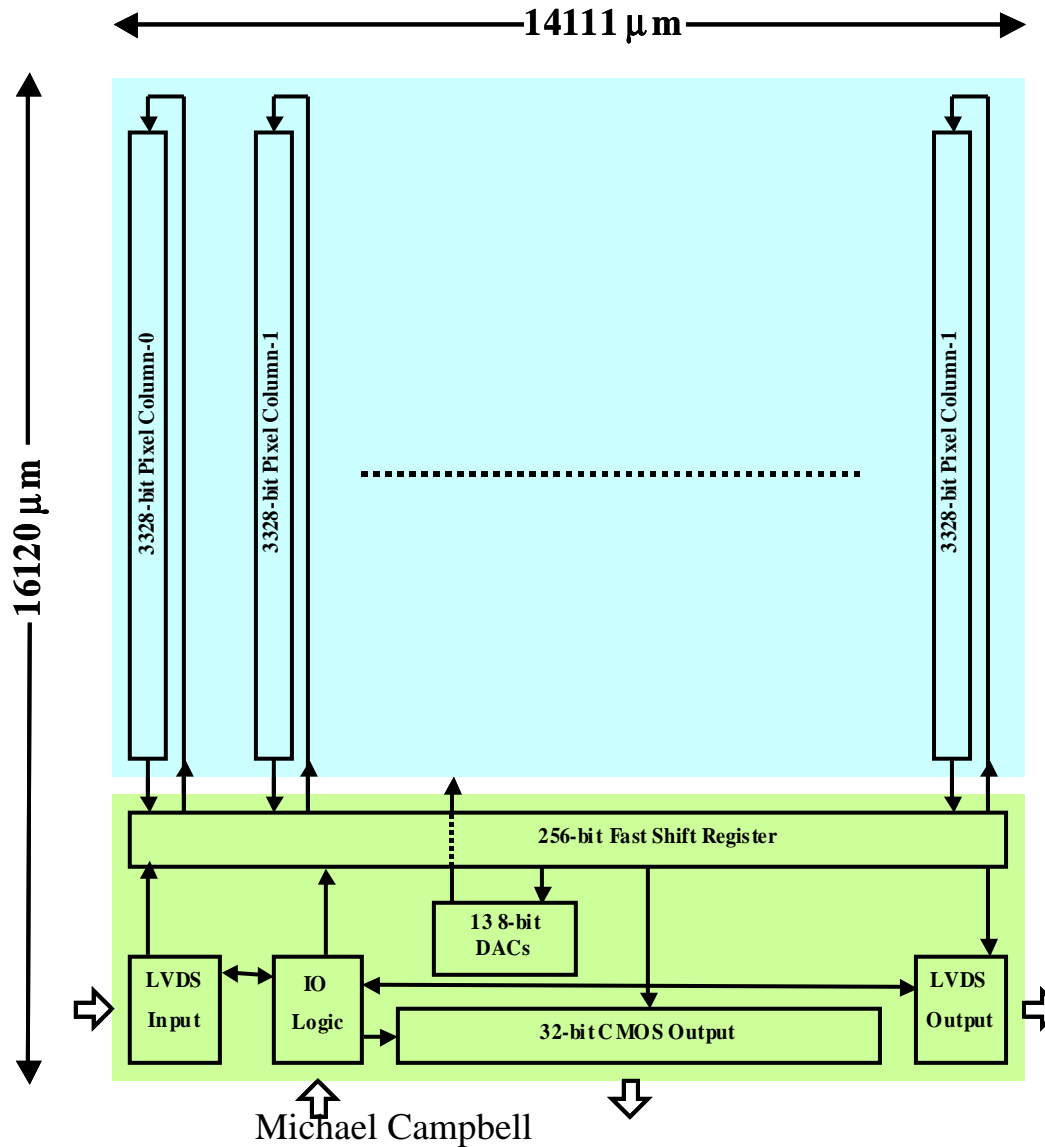
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Medipix2 Chip Architecture

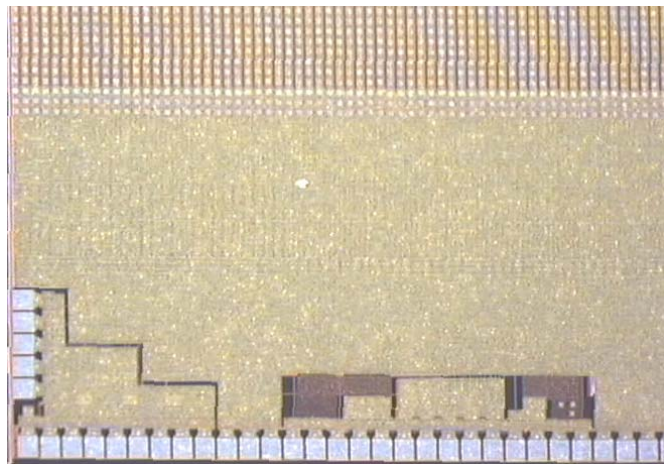
256 x 256 pixels
3ms readout time



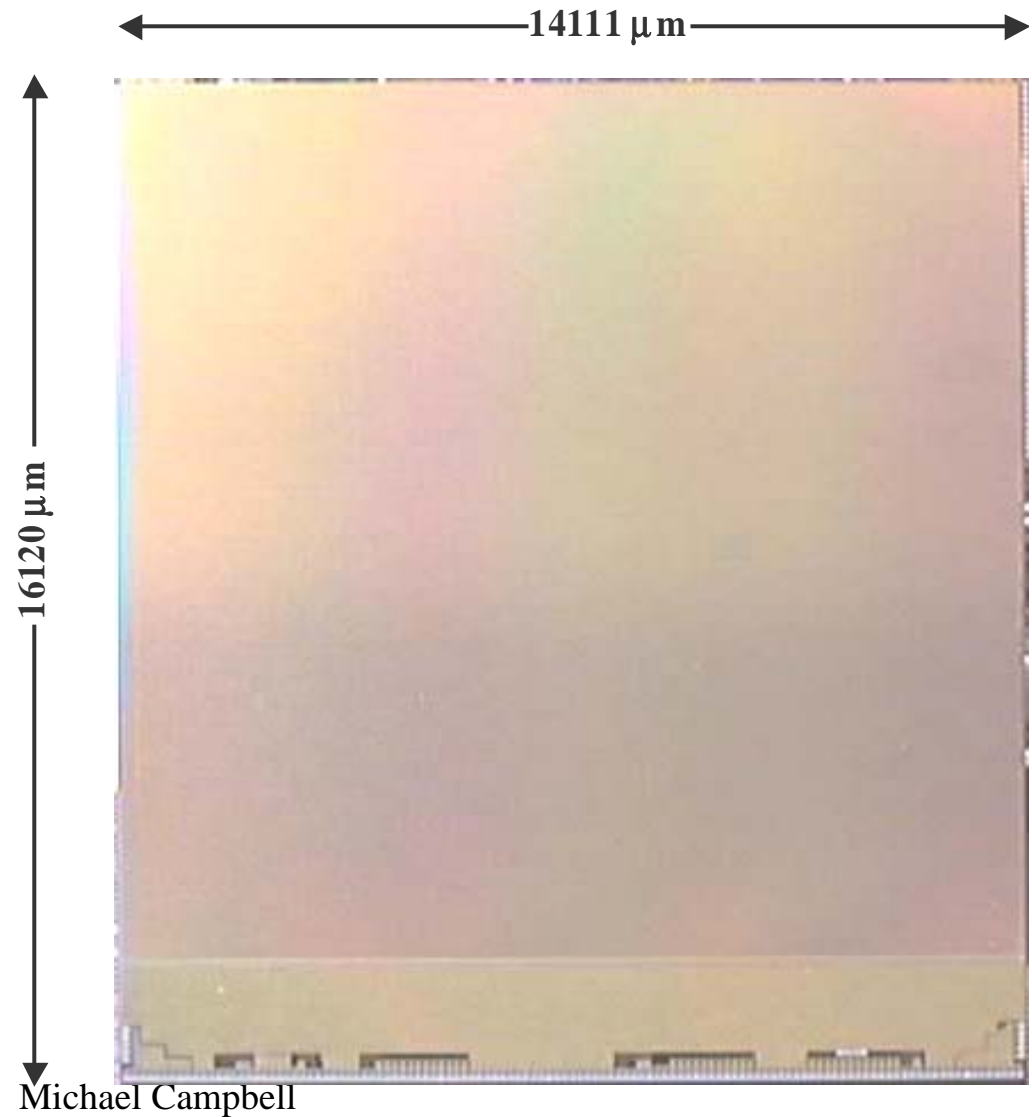
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Medipix2 Chip Architecture (II)



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Electrical measurements

	Electron Collection	Hole Collection
Gain	12.5 mV/ke	13.25 mV/ke
Non linearity	<3% to 100ke⁻	<3% to 80ke⁻
Peaking time	<150ns	
Return to baseline	<1μs for Qin <50 ke⁻	
Electronic Noise	σ_{nL}~ 110 e⁻ σ_{nH}~ 110 e⁻	
Threshold dispersion	σ_{nTHL}~ 360 e⁻ (~ 90 e⁻ tuned)	
Analog power dissipation	~8 μW/channel for 2.2V supply	



Medipix2 bump bonded to a 300 μm Si sensor

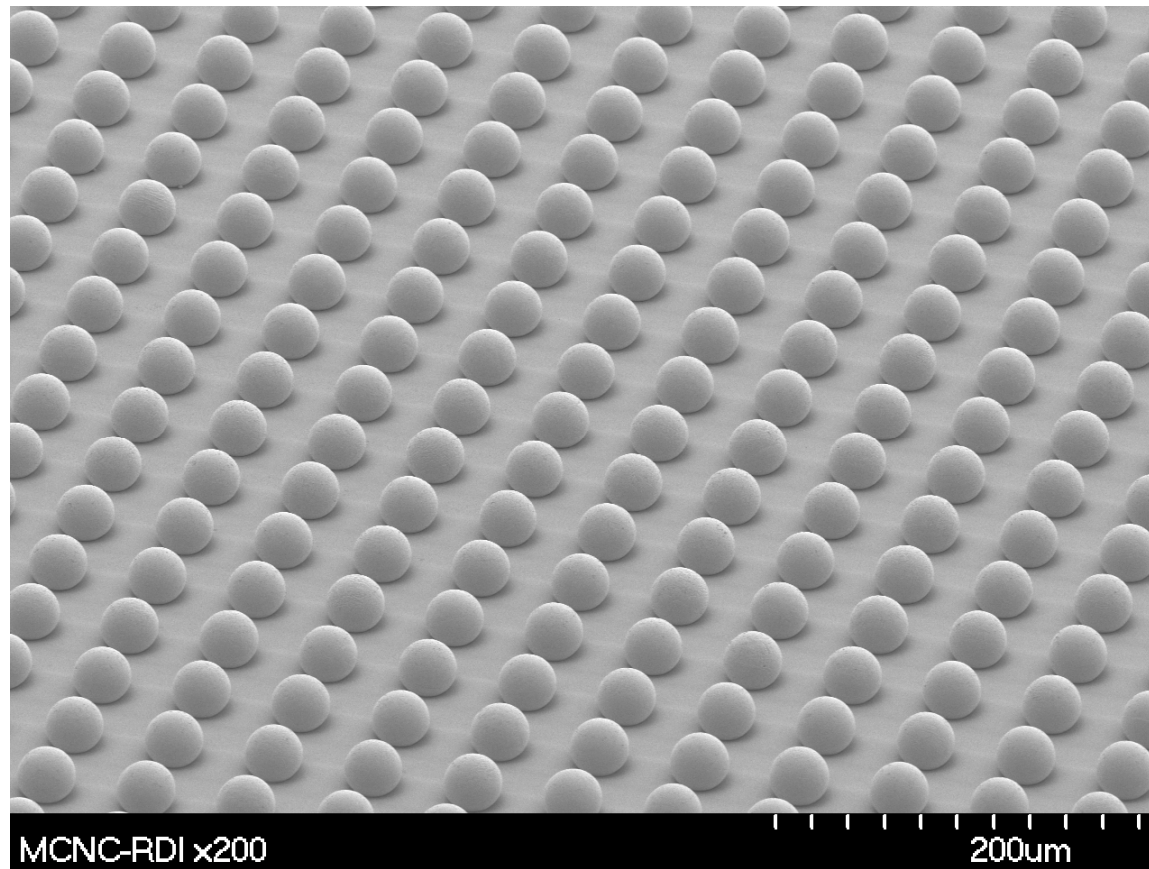


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Bumps of readout side

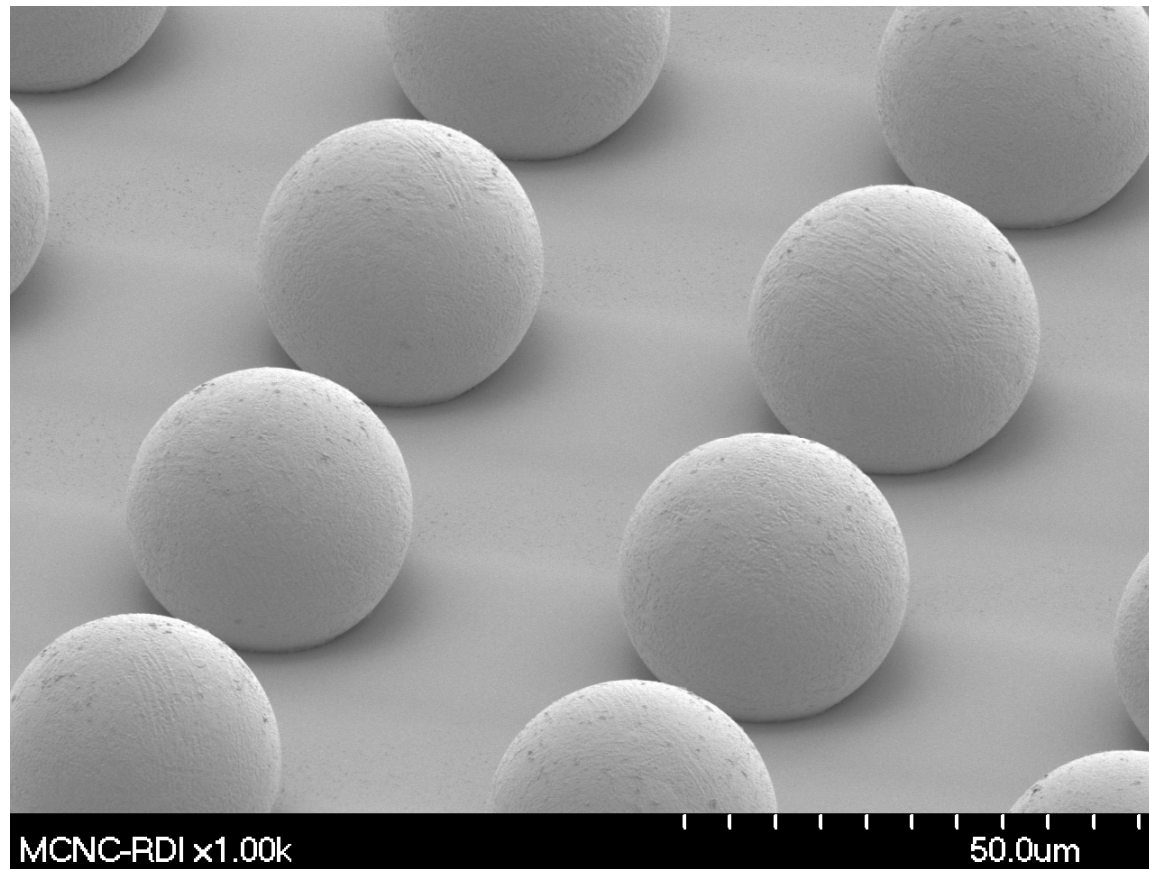


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Bumps of readout side – close up

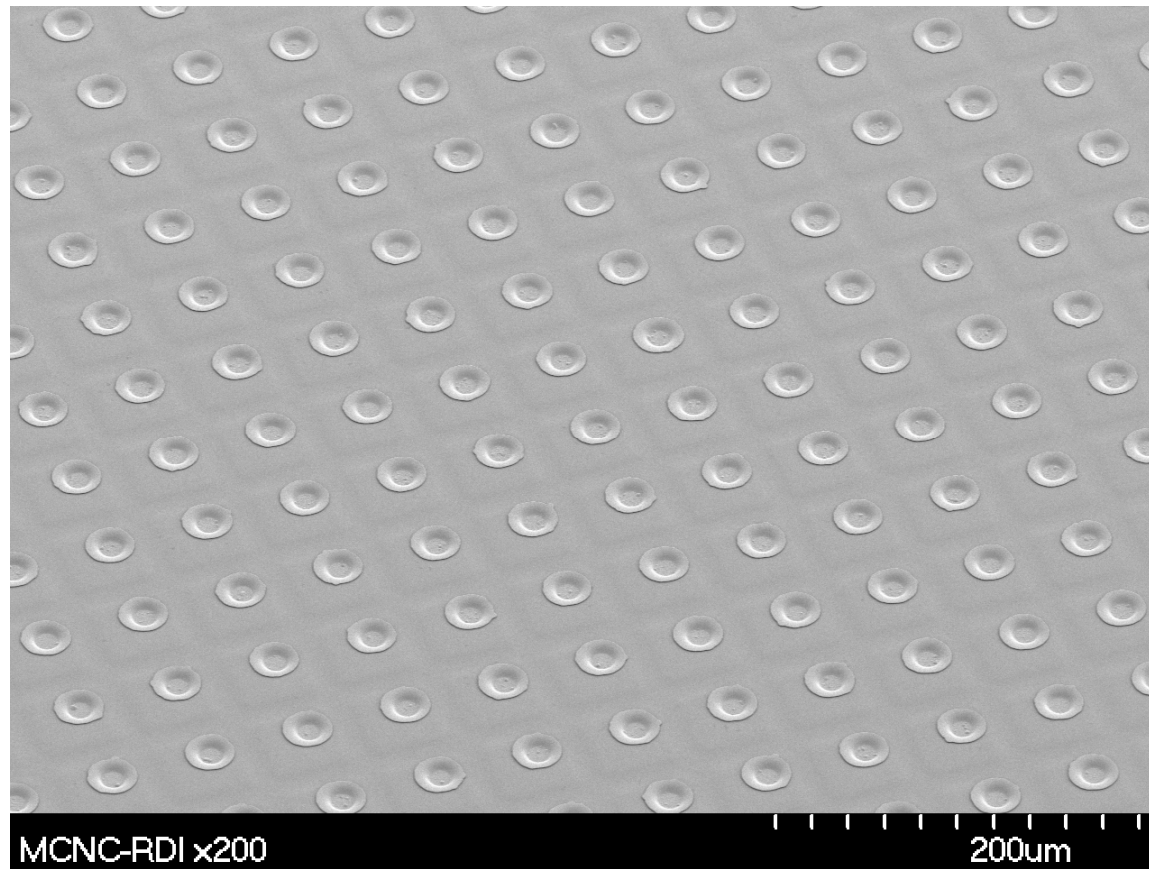


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Under bump metallization on sensor side

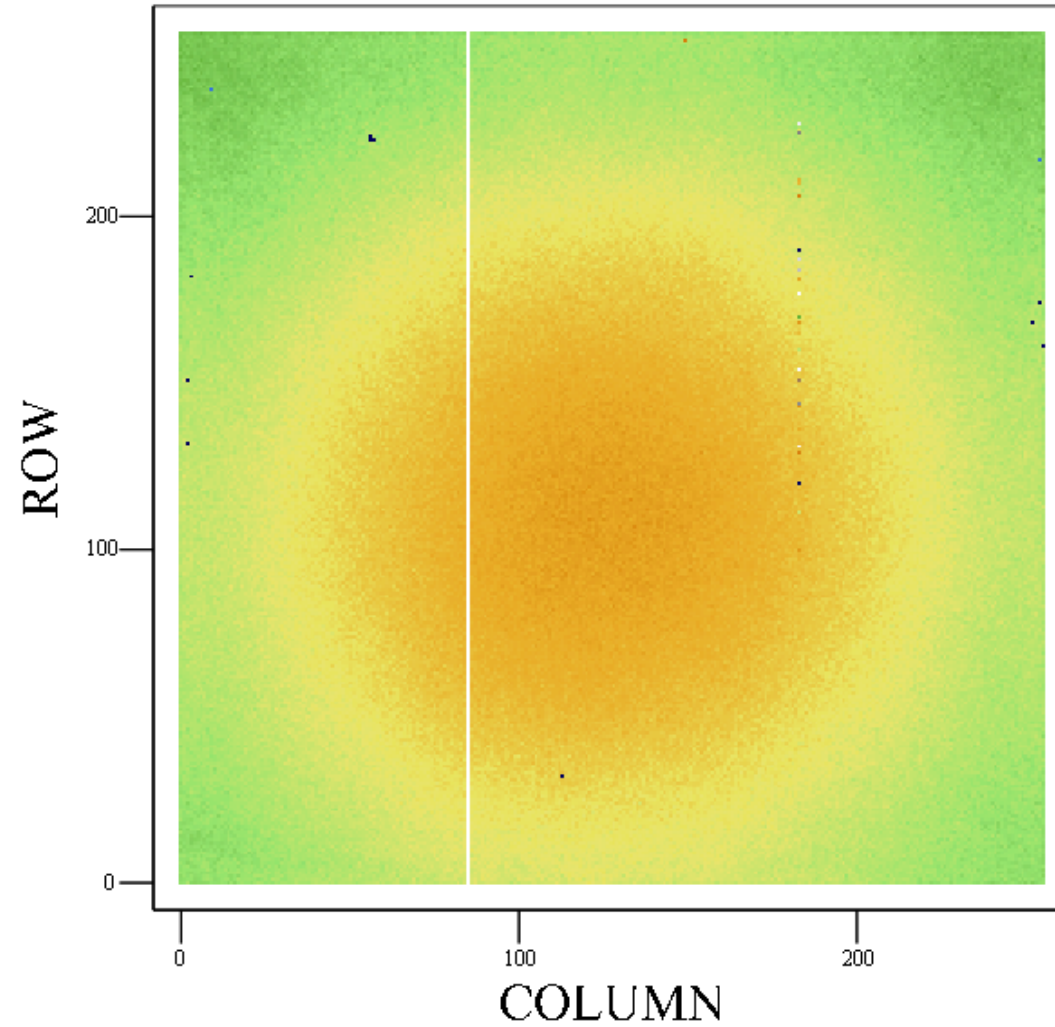


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Response to ^{109}Cd source



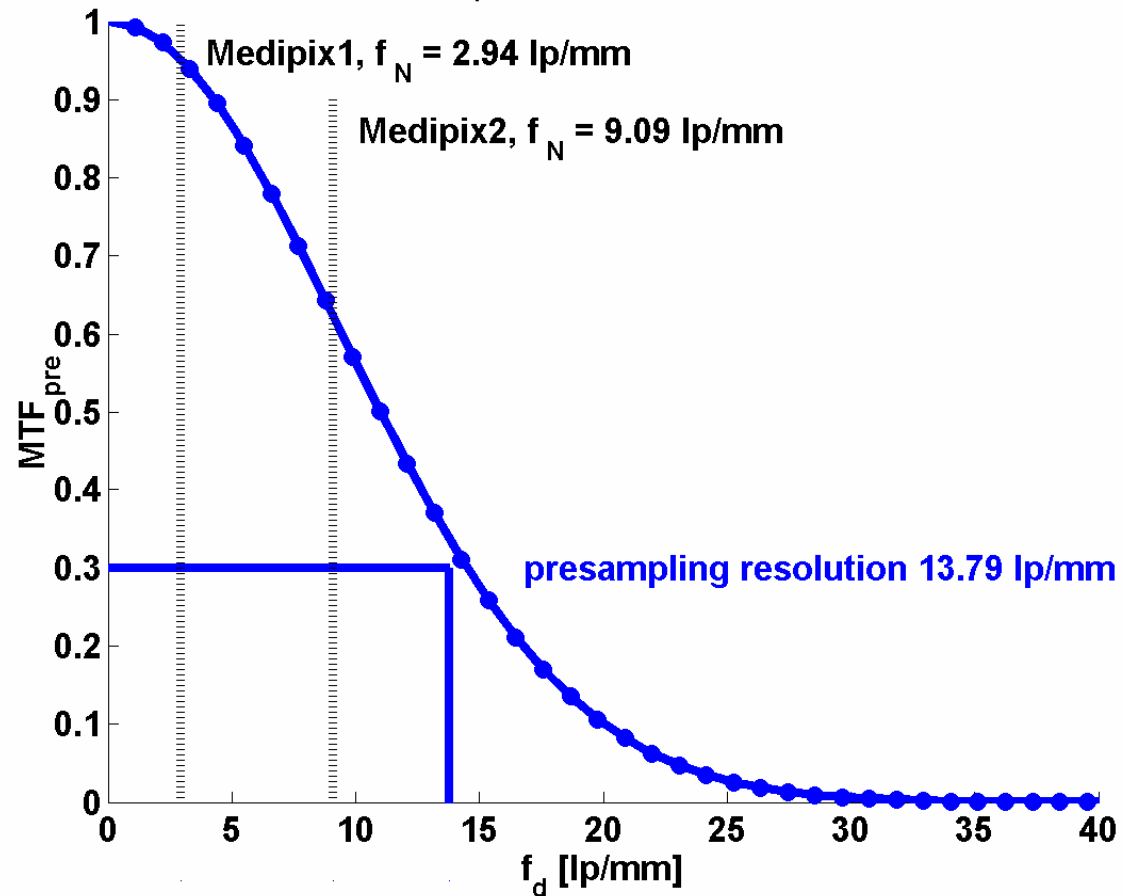
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MTF of Medipix2 and 300 μm thick Si detector using x-ray machine

MTF_{pre}, S3_D3, THL=182

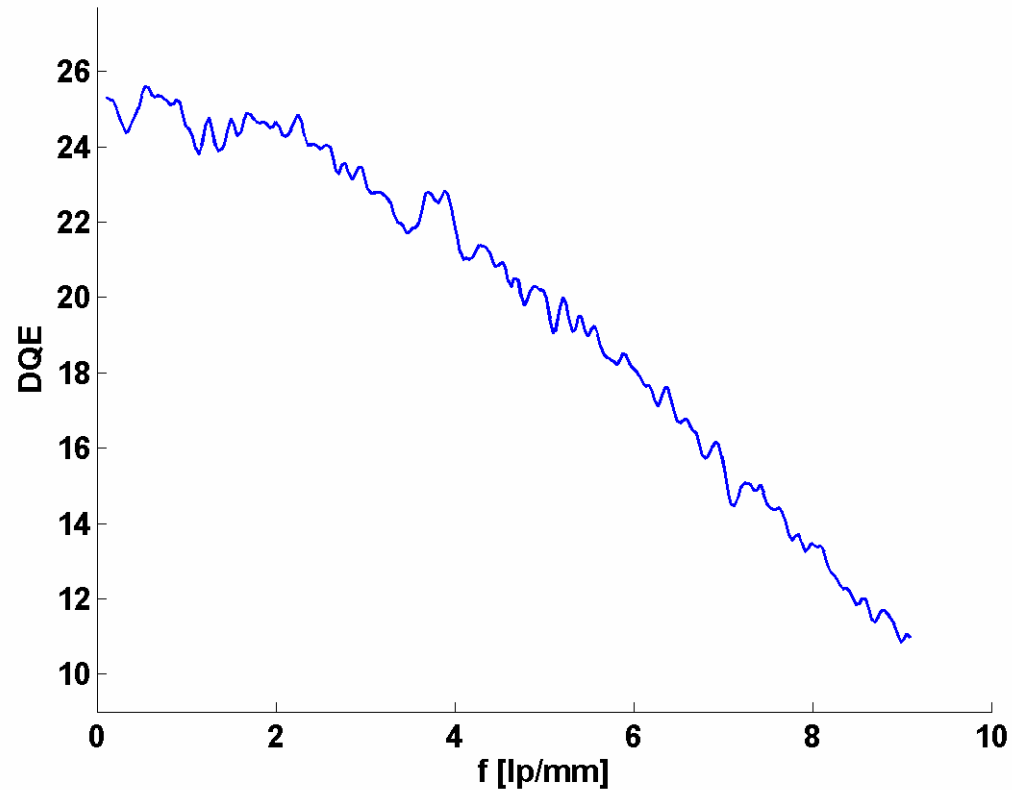


Measurement taken using a Seifert FK61-04x12 X-ray source, W target, 25kV, and a filter equivalent to 2.5 mm of Al.



DQE of Medipix2 and 300 μm thick Si detector using x-ray machine

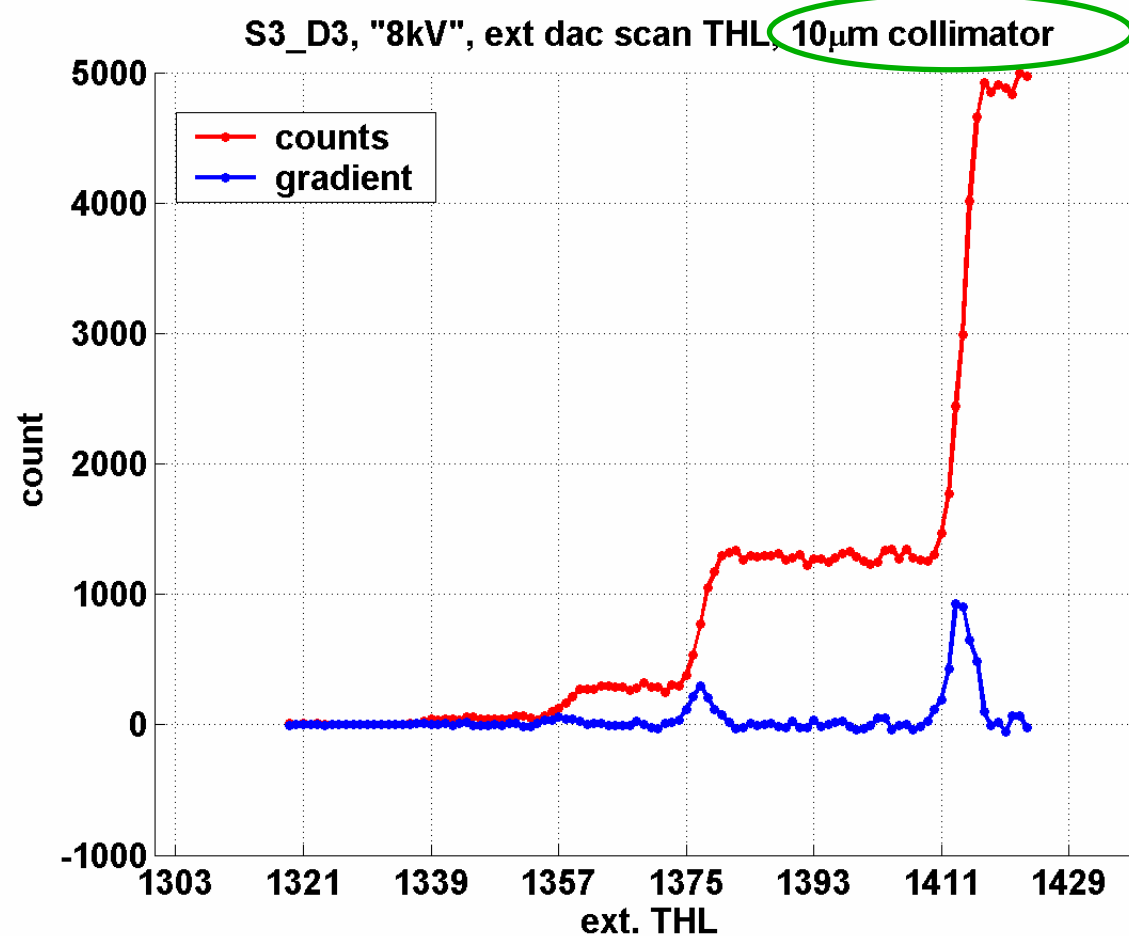
DQE, MPX2, W25kV



Measurement taken using a Seifert FK61-04x12 X-ray source, W target, 25kV, and a filter equivalent to 2.5 mm of Al. Agrees with theoretical calculation.



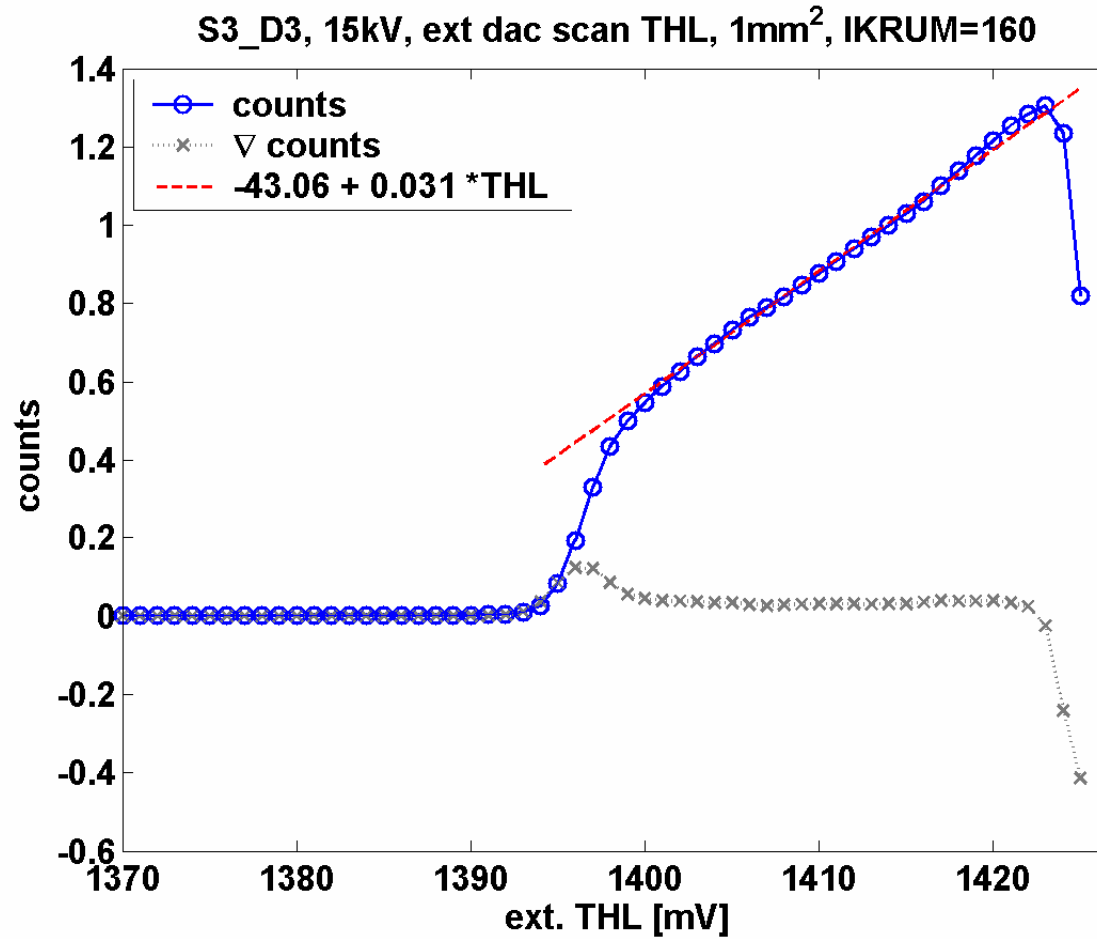
Calibration at ESRF – monochromatic pencil beam at pixel centre



Increasing threshold 8keV plus harmonics....



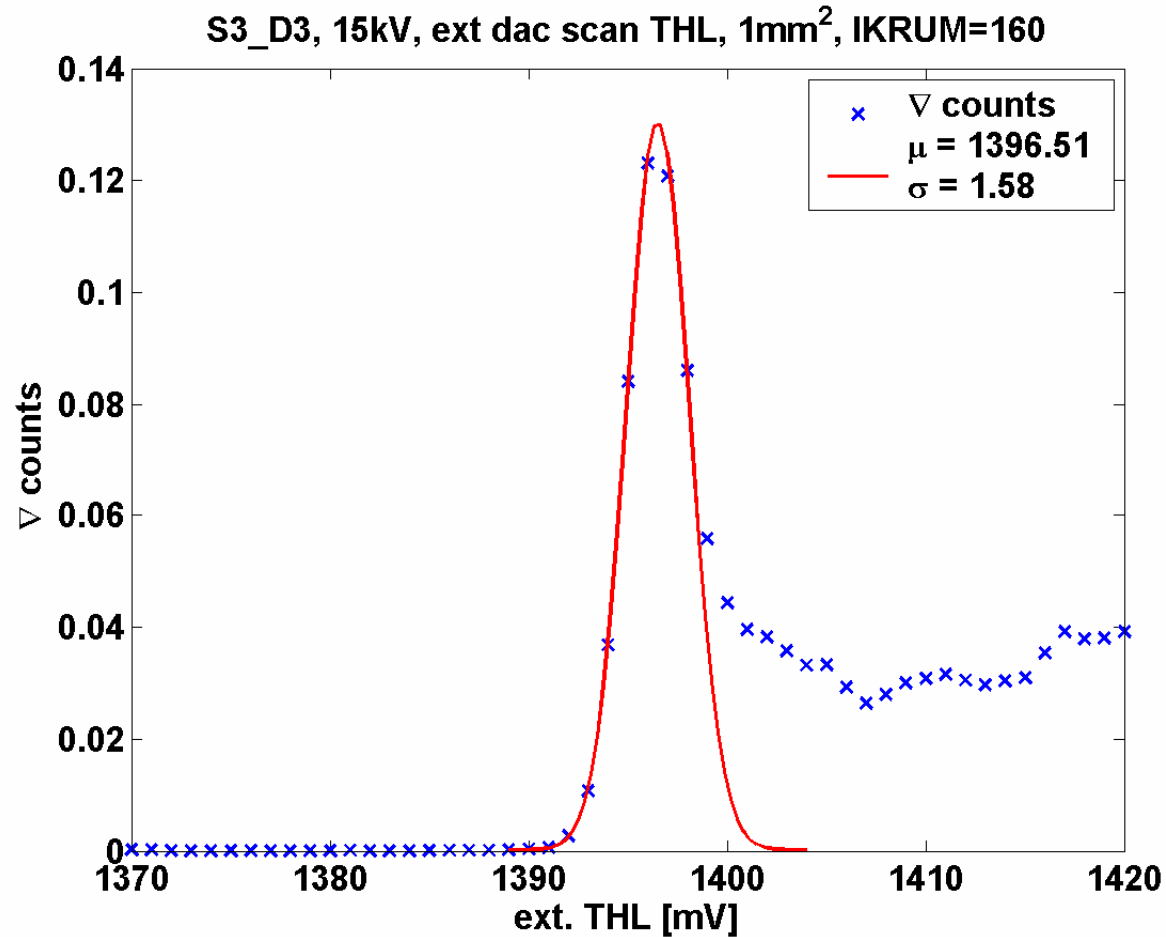
Effect of Charge Sharing on Energy Resolution – monochromatic 1mm² beam



← Increasing threshold



Effect of Charge Sharing on Energy Resolution – monochromatic 1mm² beam



← Increasing threshold



The implications of charge sharing between pixels

- ◆ **Pixel-to-pixel threshold variation together with charge sharing implies that flat field correction is necessary when image statistics approach or exceed threshold variation induced count spread**
- ◆ **Flat field correction becomes sensitive to incoming spectrum**
- ◆ **But solutions are possible (see further work)**

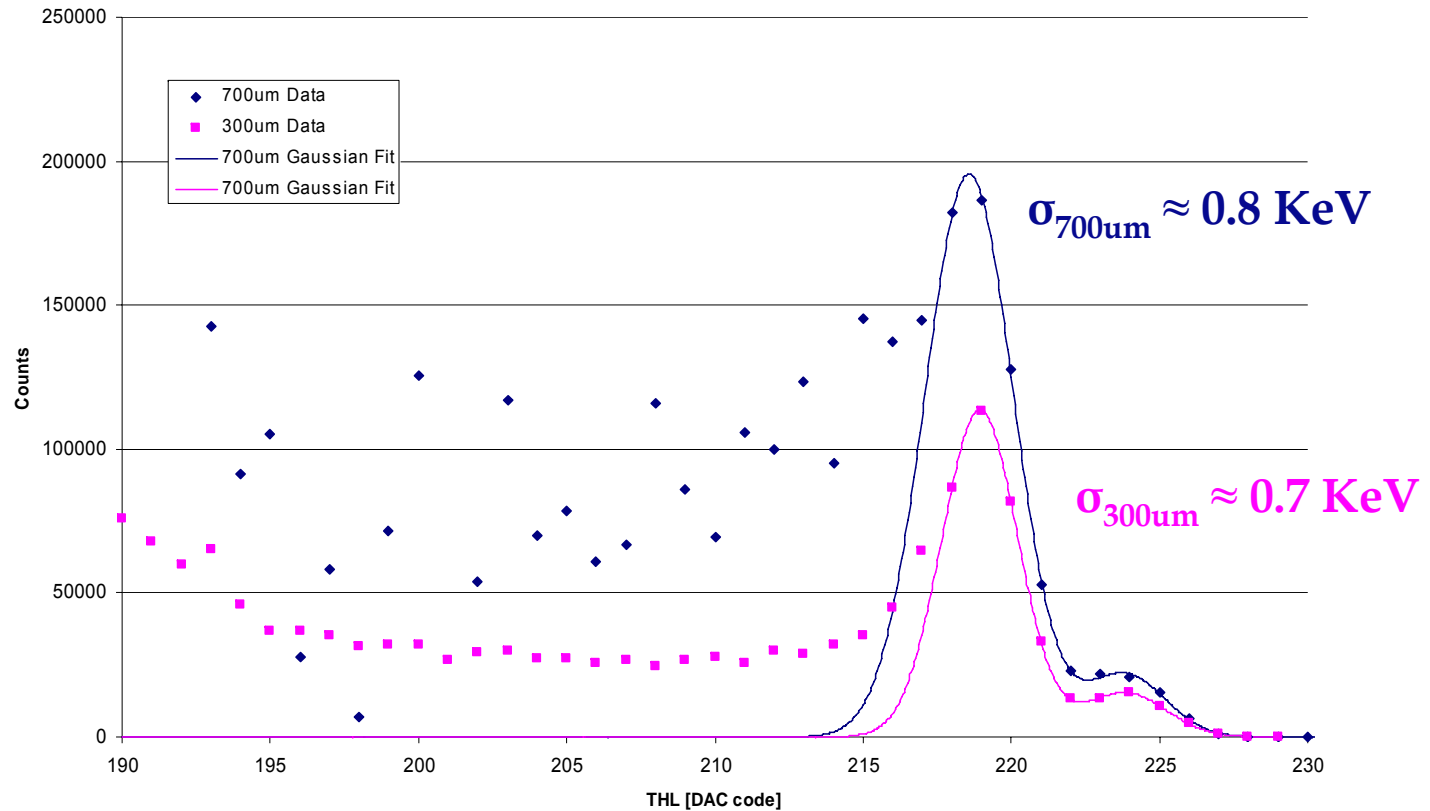


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Spectrum of ^{109}Cd Source

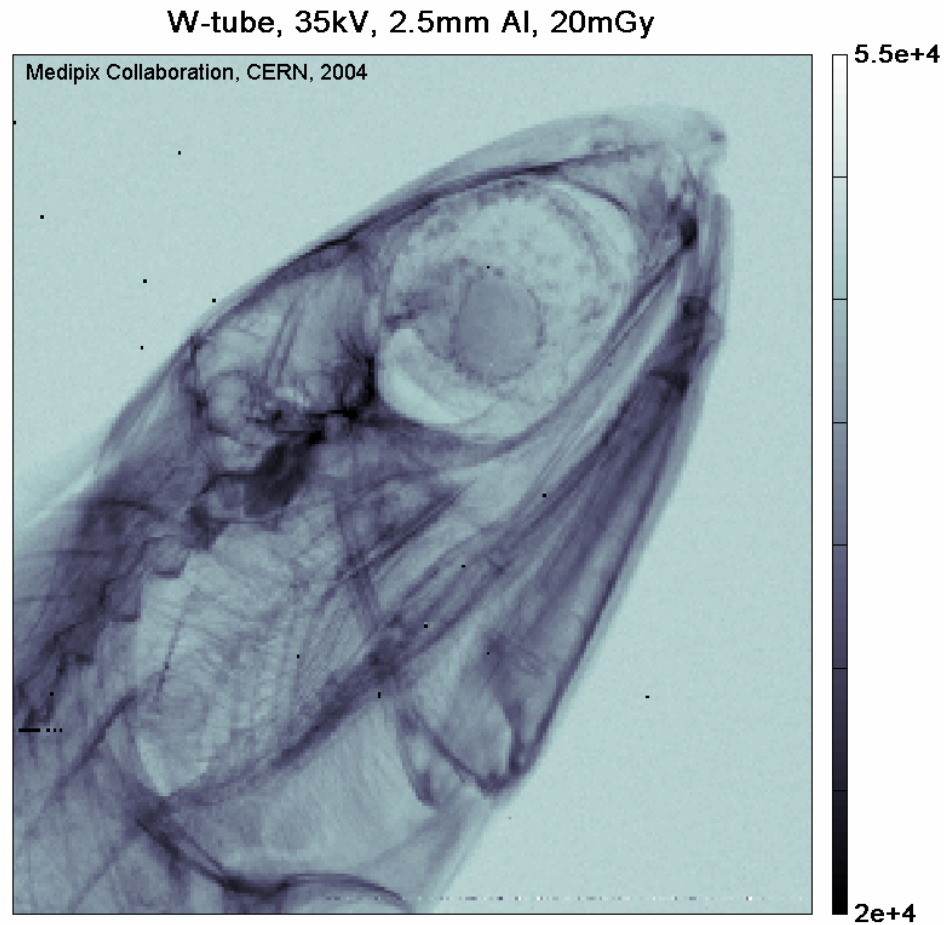


Increasing threshold

Spectra obtained summing the response of all pixels using 300 μm and 700 μm thick Si sensors.



Image of a dried anchovy



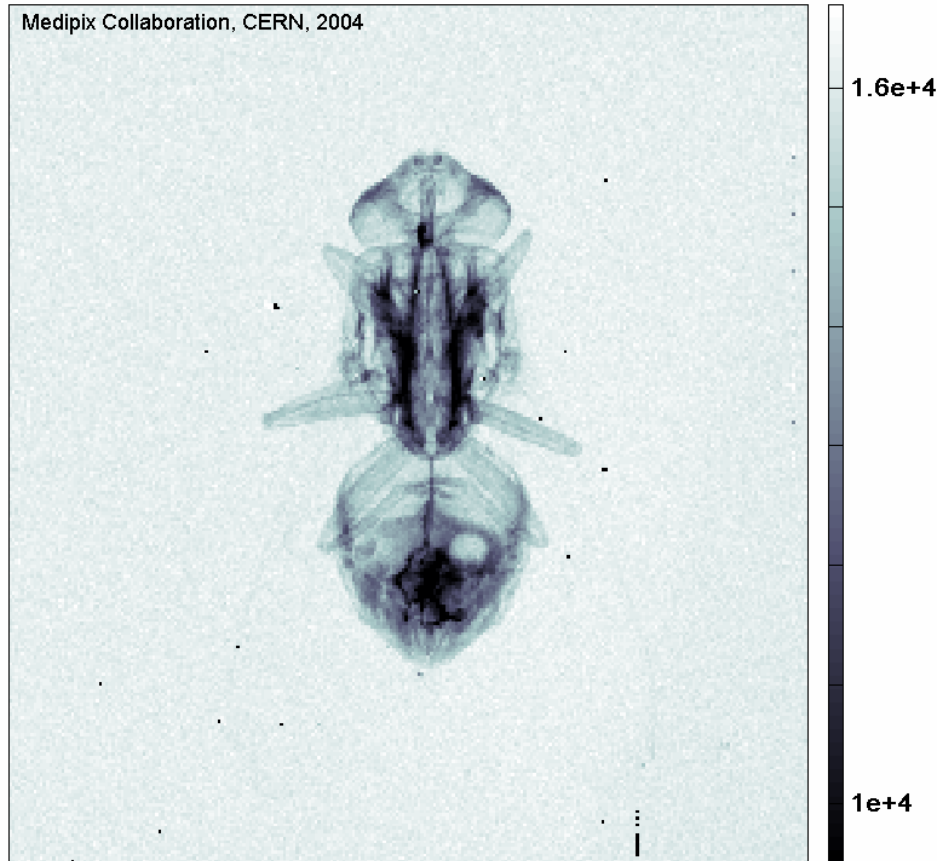
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Image of a fly

W-tube, 14kV, 125 μm Al, 5mm PMMA

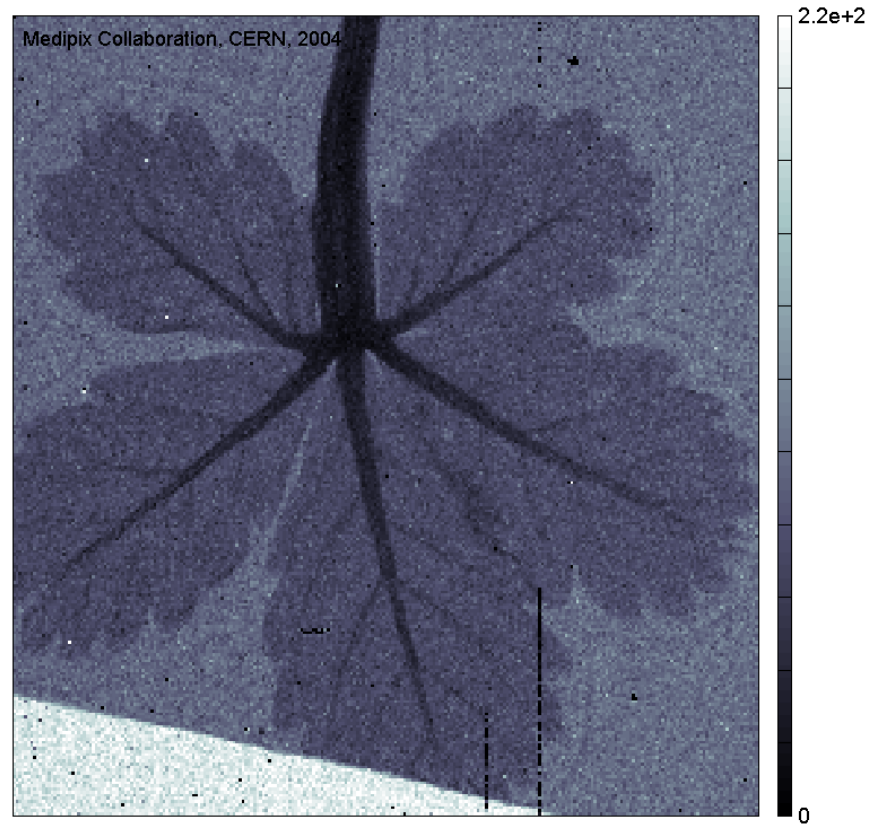


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Image of a leaf (^{55}Fe)

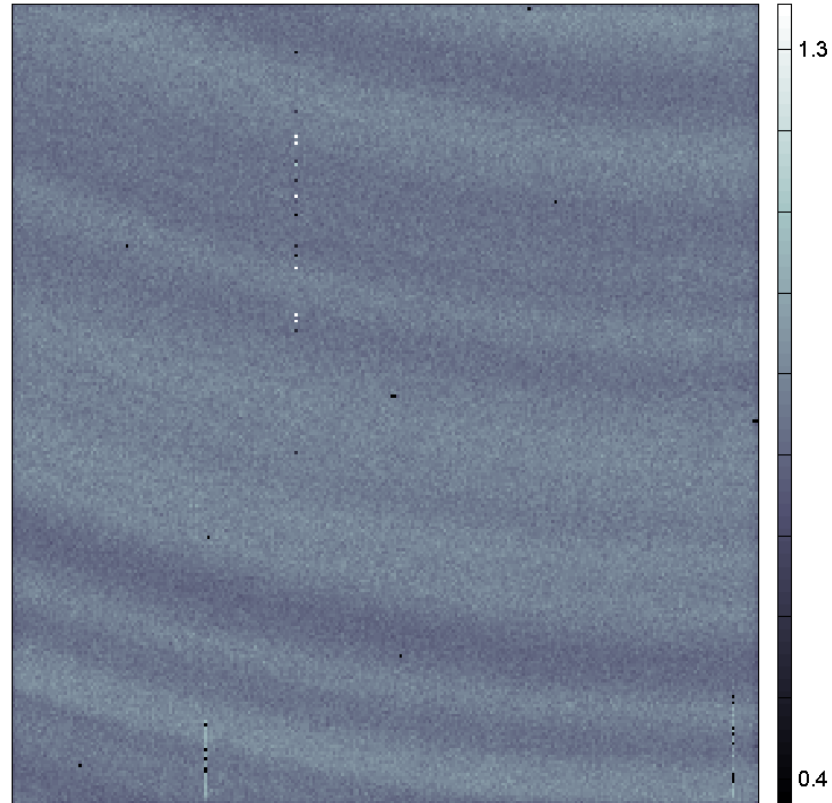


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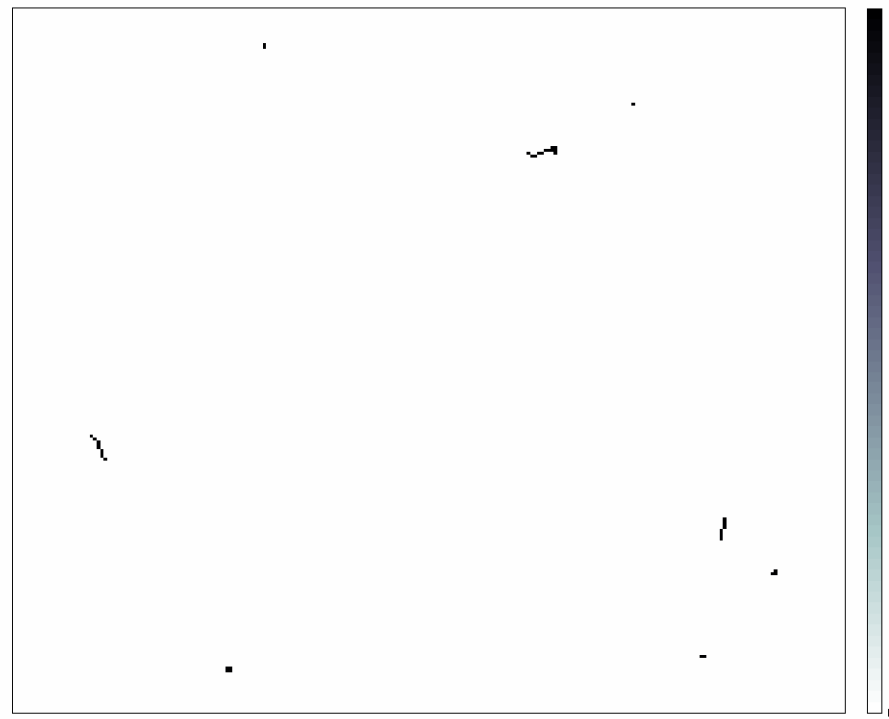
Detector inhomogeneities using Medipxi2



Flood image taken using an x-ray source and an under-depleted sensor. The image has been corrected with a flat filed correction map taken using a the same setup in over-depletion.



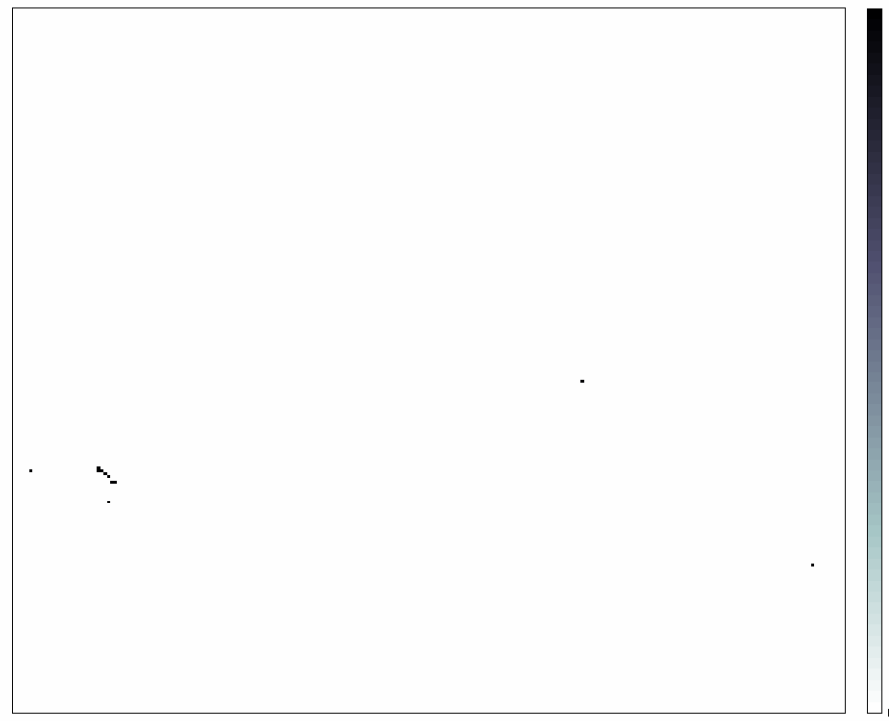
Background radiation - 1



Exposure of 1 min - no source in vicinity



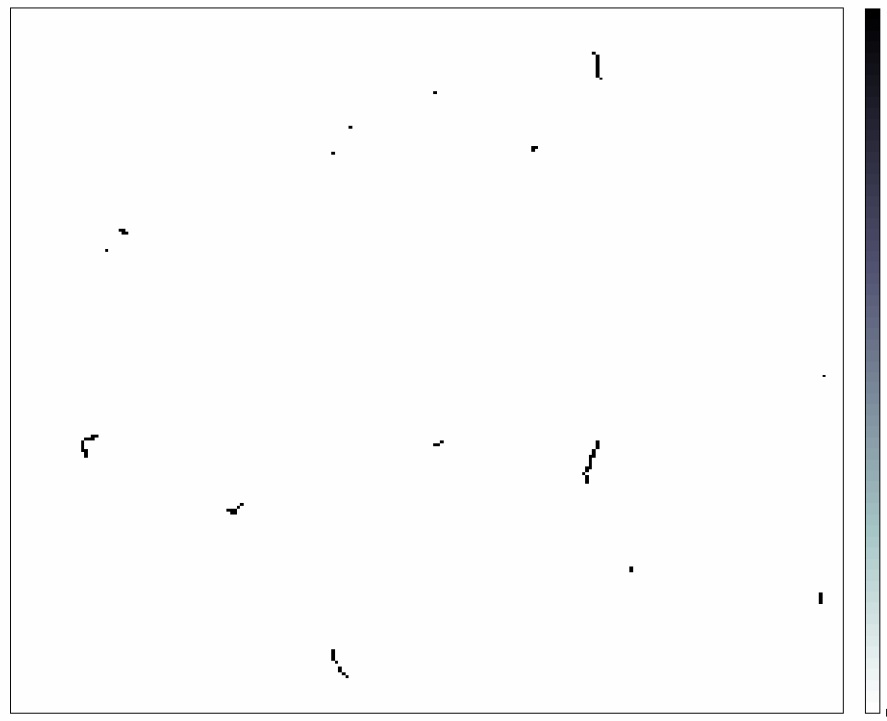
Background radiation - 2



Exposure of 1 min - no source in vicinity



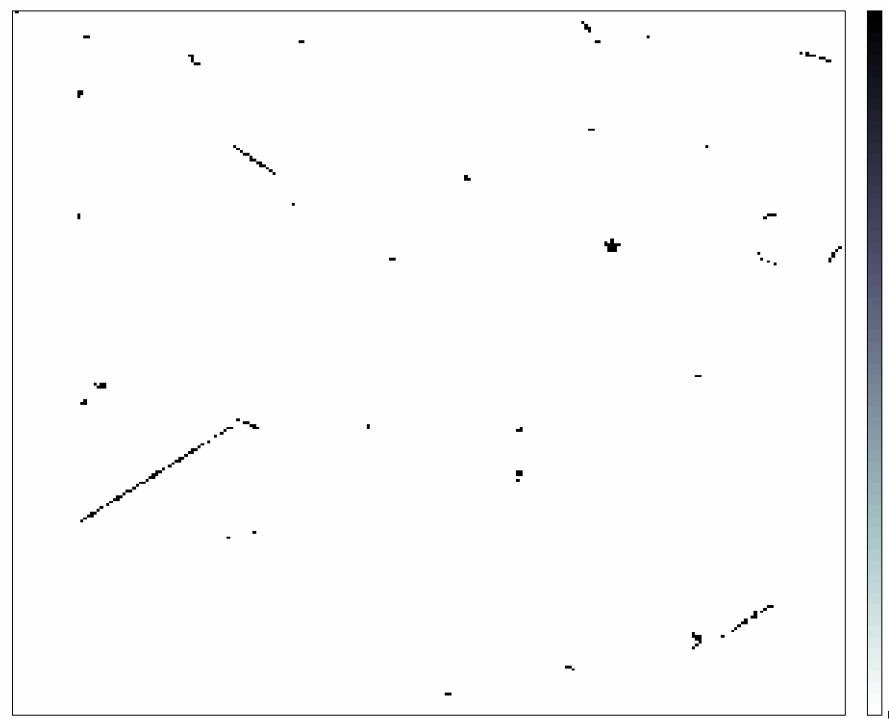
Background radiation - 3



Exposure of 1 min - no source in vicinity



Background radiation - 4



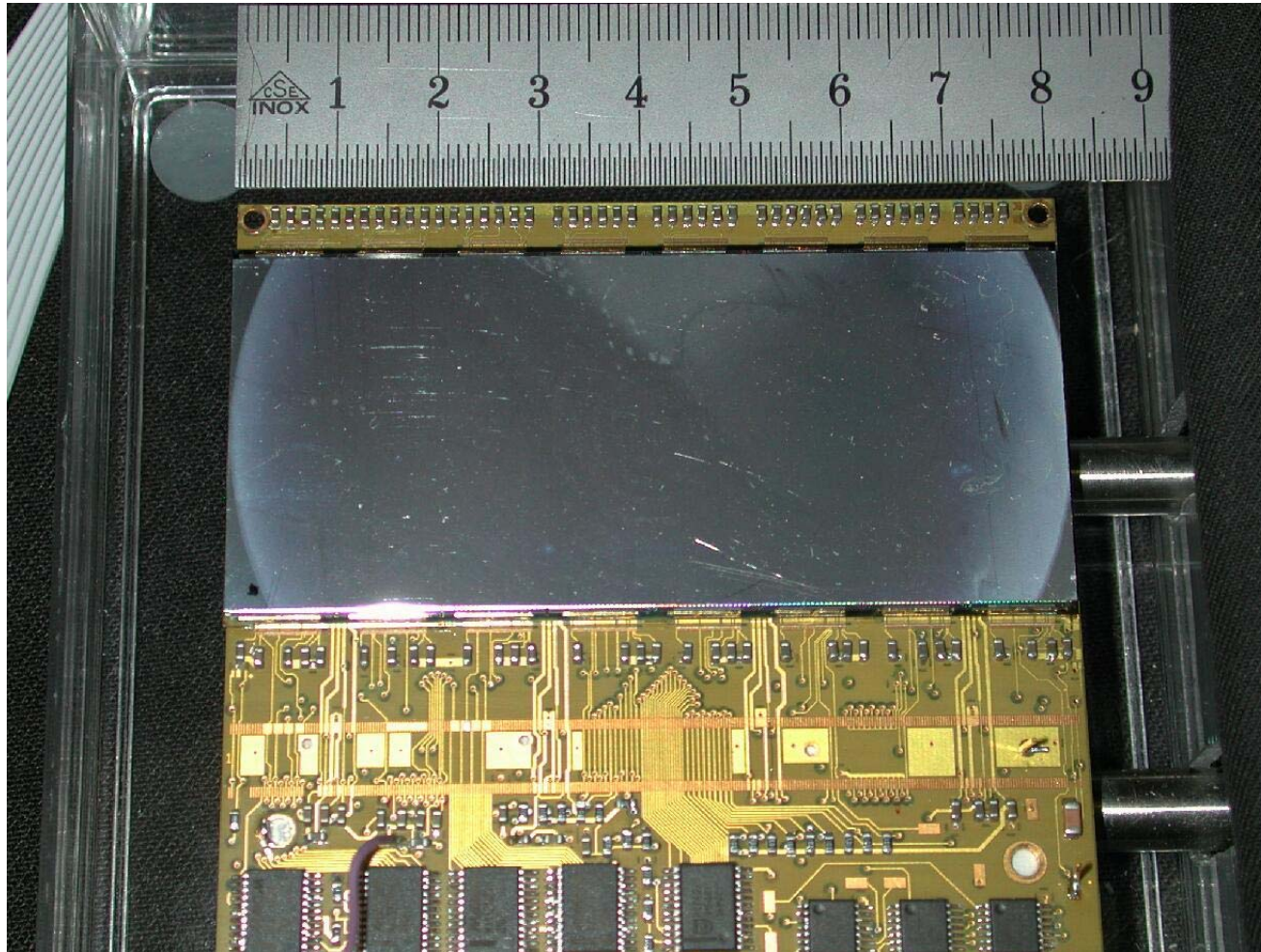
Exposure of 1 min - no source in vicinity



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PILATUS Module Typ I (readout electronics flat)

Ch. Brönnimann,
SLS Detector Group



Module Data

- Active Area: 79.6 x 35.3 mm² (continuously sensitive)
- 157 x 366 = 57462 pixels
- 16 chips (radiation hard)
- Pixel size 0.217x0.217 mm²
- Readout-time: 6.7 ms
- Energy Range: $E_\gamma > 4.5$ keV
- Minimum Threshold: 3 keV
- Threshold adjust per pixel
- Threshold RMS 6% of threshold
- Rate: ~10KHz/pixel
- 15-bit counter/pixel
- single photon counting, no readout noise



- Largest pixel detector array for SR
- 6 banks a 3 modules, 1120 x 967 pixels
- Area: 21 x 24 cm²
- 288 chips->~300x10⁶ transistors
- Readout time: 6.7ms
- Currently 2 frames/s
- goal 10 frames/ s
- Active area: 85%
- Moderate count rates (<10kHz/pixel)

Benefits for PX:

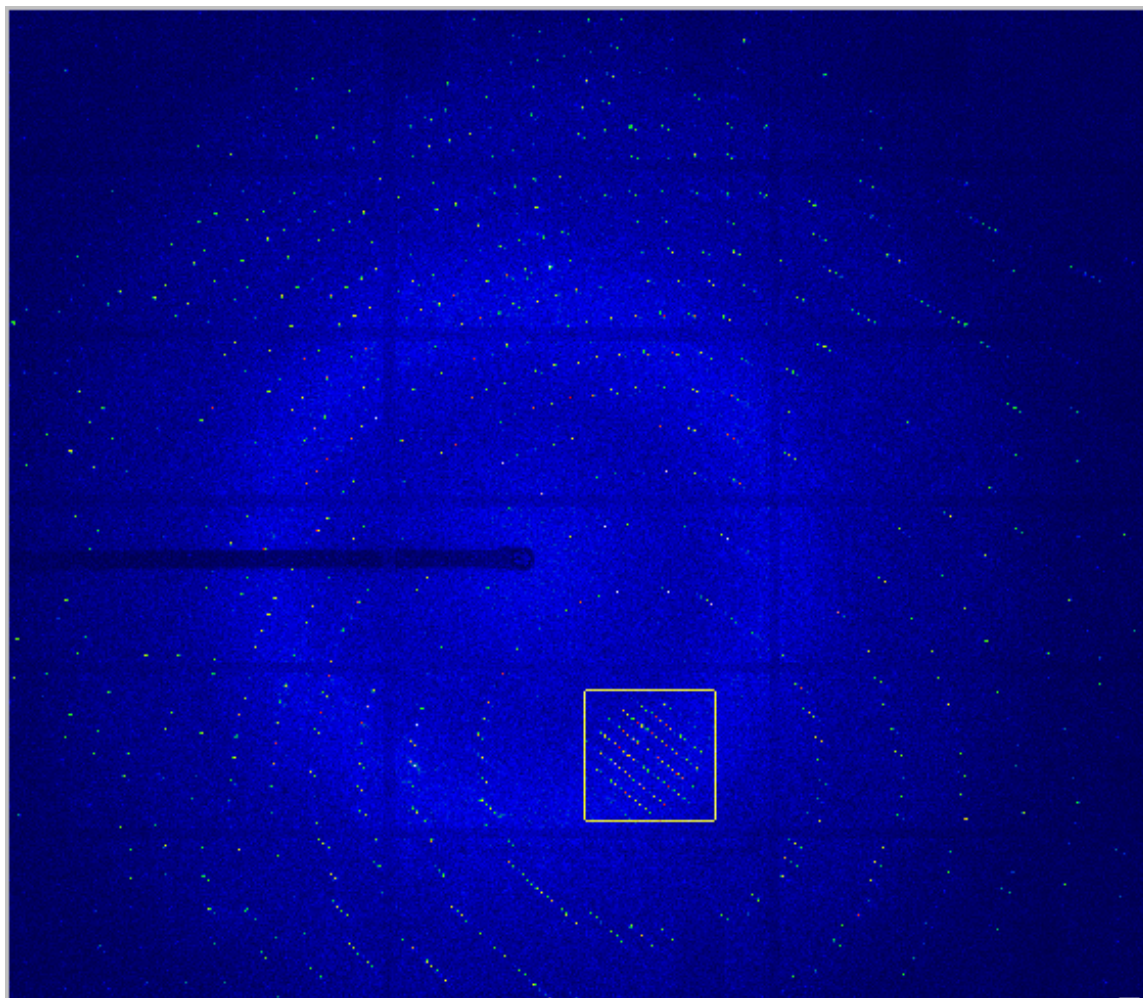
- Single Photon Counting-> Excellent S/N ratio for weak reflections
- Short read-out time -> Fine- ϕ -slicing





PSI

PAUL SCHERRER INSTITUT SLS Detector Group



Thaumatin

90° data-set,
0.5s, 0.5°
11.9 keV

Beam intensity 0.68%

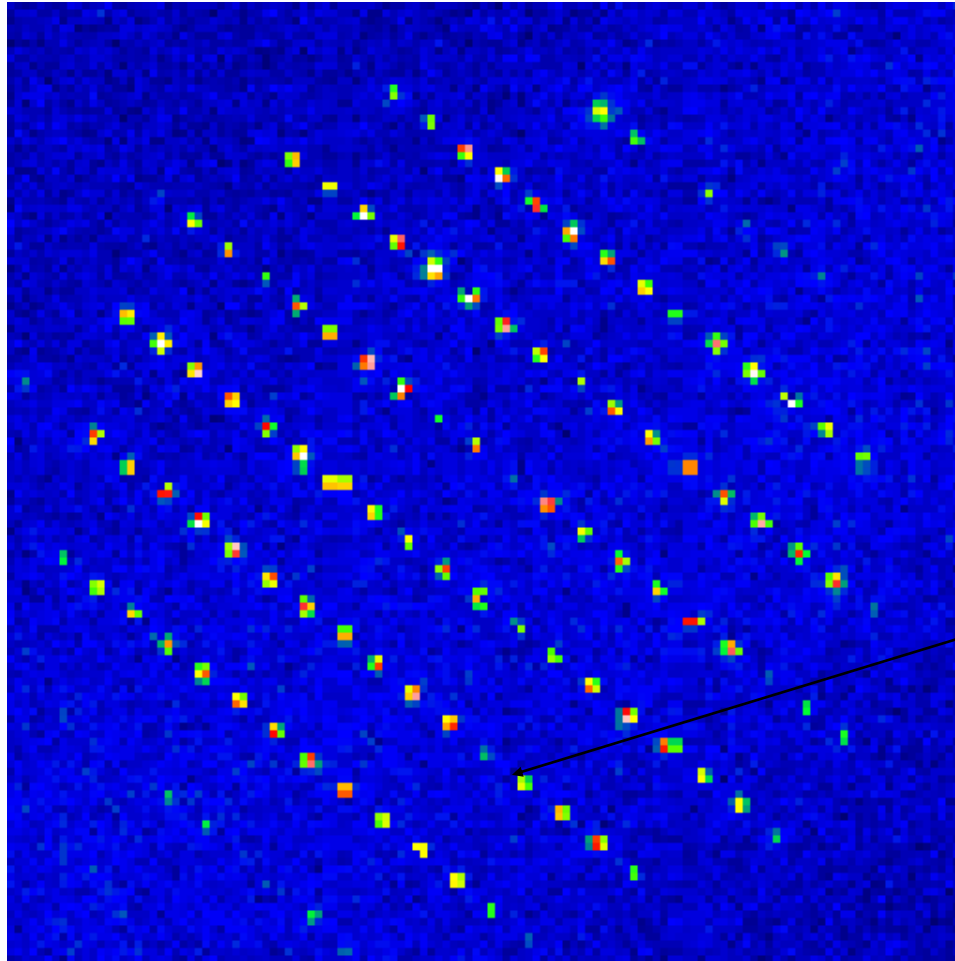
(fully corrected
image)



PSI

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SLS Detector Group



Thaumatin
(zoom in)
0.5s, 0.5°
11.9 keV

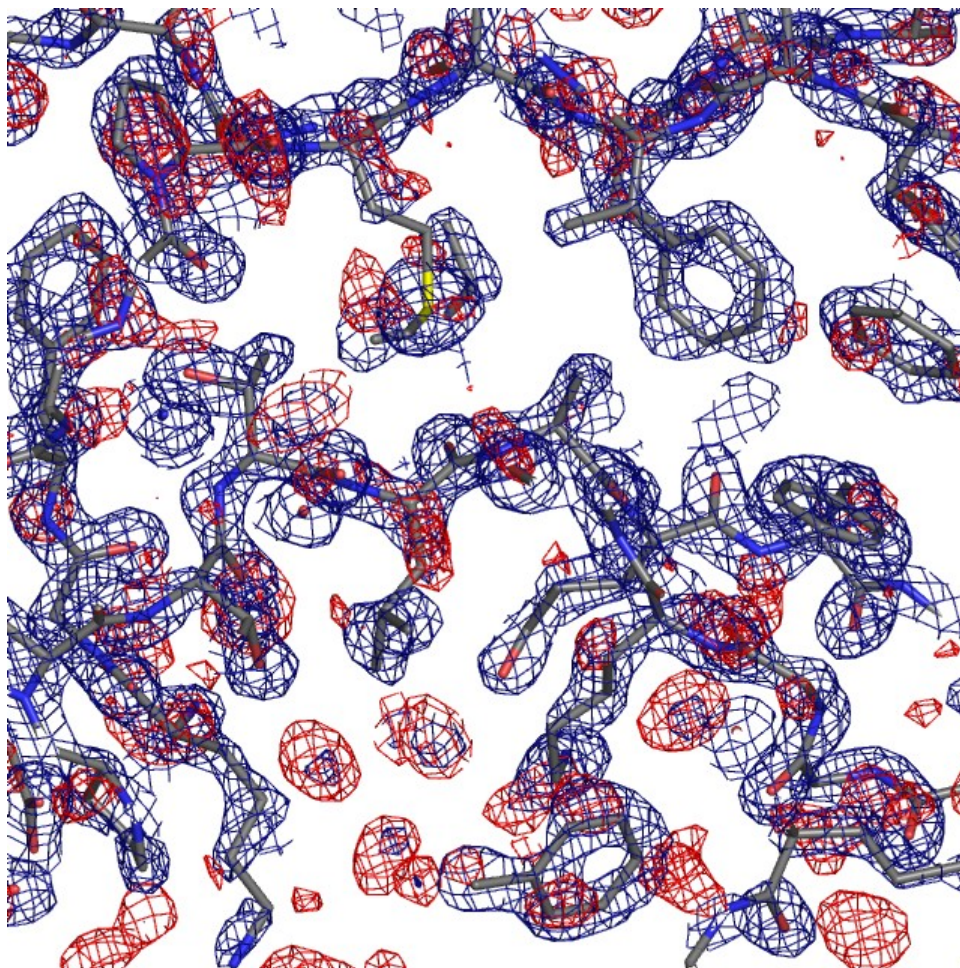
Very good point spread function
-> Very sharp reflections



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SLS Detector Group



Preliminary thaumatin electron density map

Processing with XDS

$R_{\text{sym}} \sim 10\%$

Resolution: 1.5 Å

Refinement:
R-Factor 28%

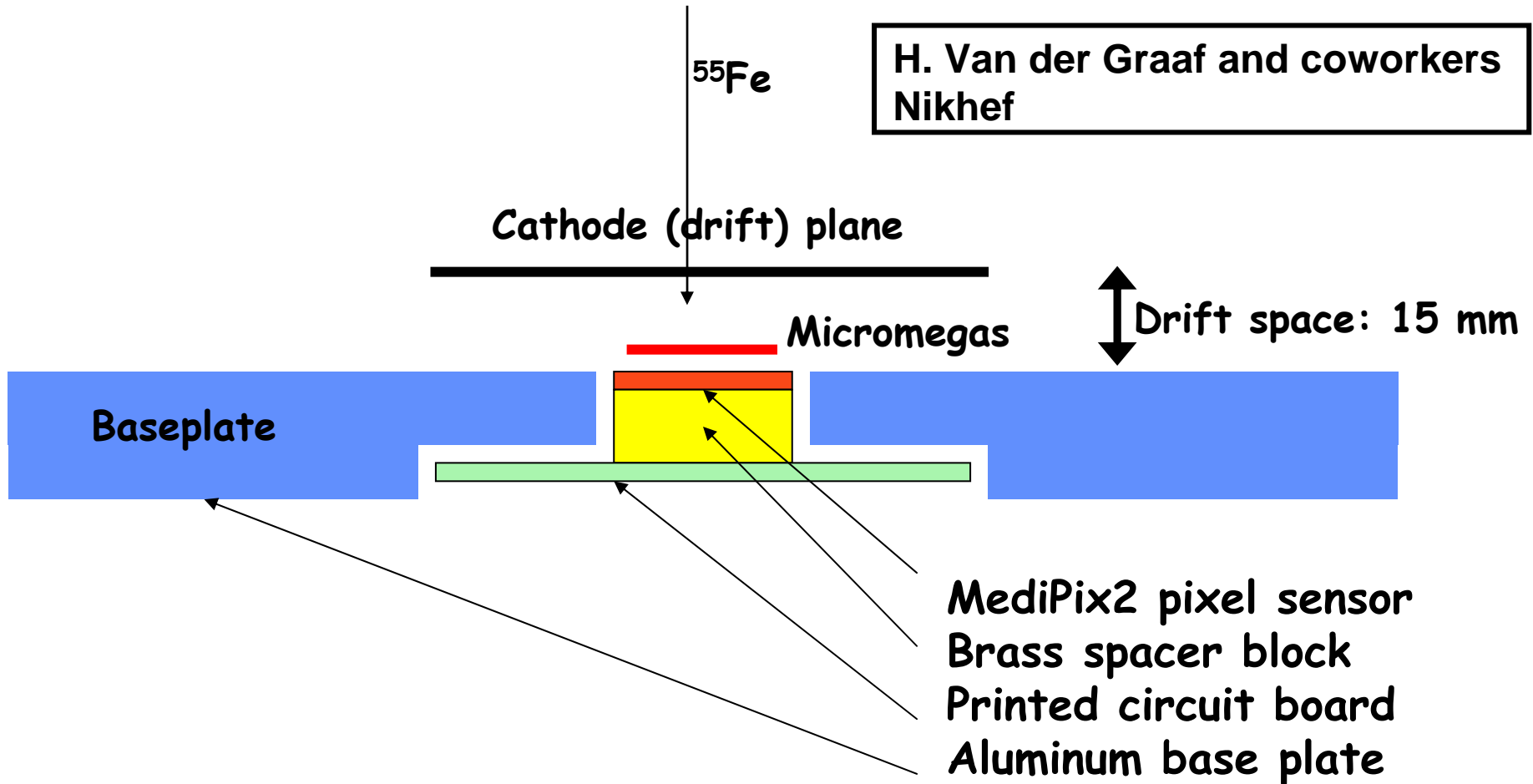
blue contours: $2 \cdot F_o - F_c$ (2sigma)

red contours: $F_o - F_c$ (2sigma)



Single electron detection using Medipix2

H. Van der Graaf and coworkers
Nikhef



Very strong E-field above (CMOS) MediPix!

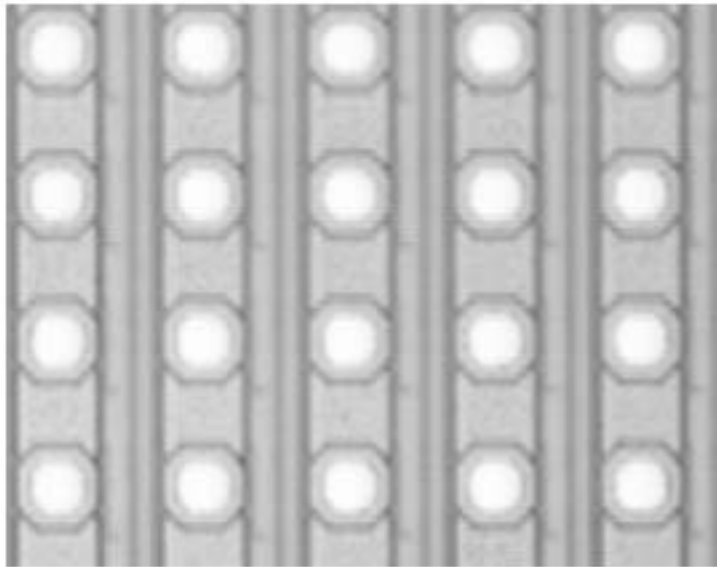
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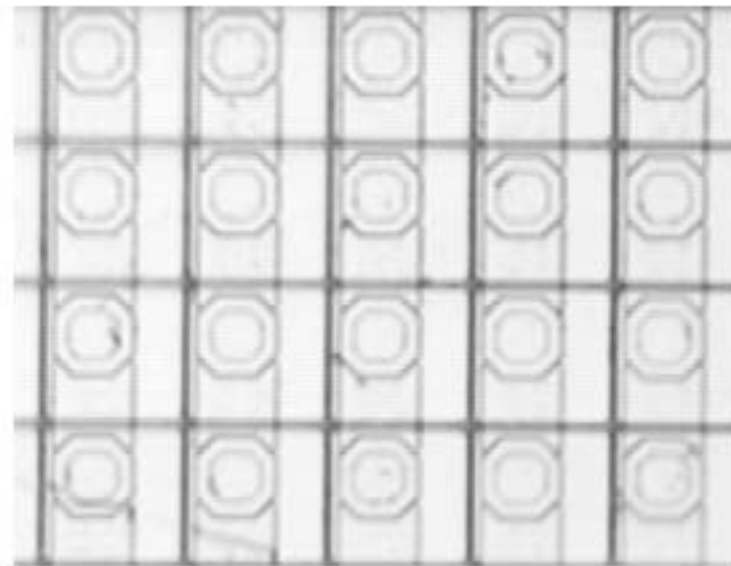
Chip post processing

MediPix modified by MESA+, Univ. of Twente, The Netherlands



a)

Pixel Pitch: $55 \times 55 \mu\text{m}^2$
Bump Bond pad: $25 \mu\text{m}$ octagonal
75 % surface: passivation SiN
New Pixel Pad: $45 \times 45 \mu\text{m}^2$

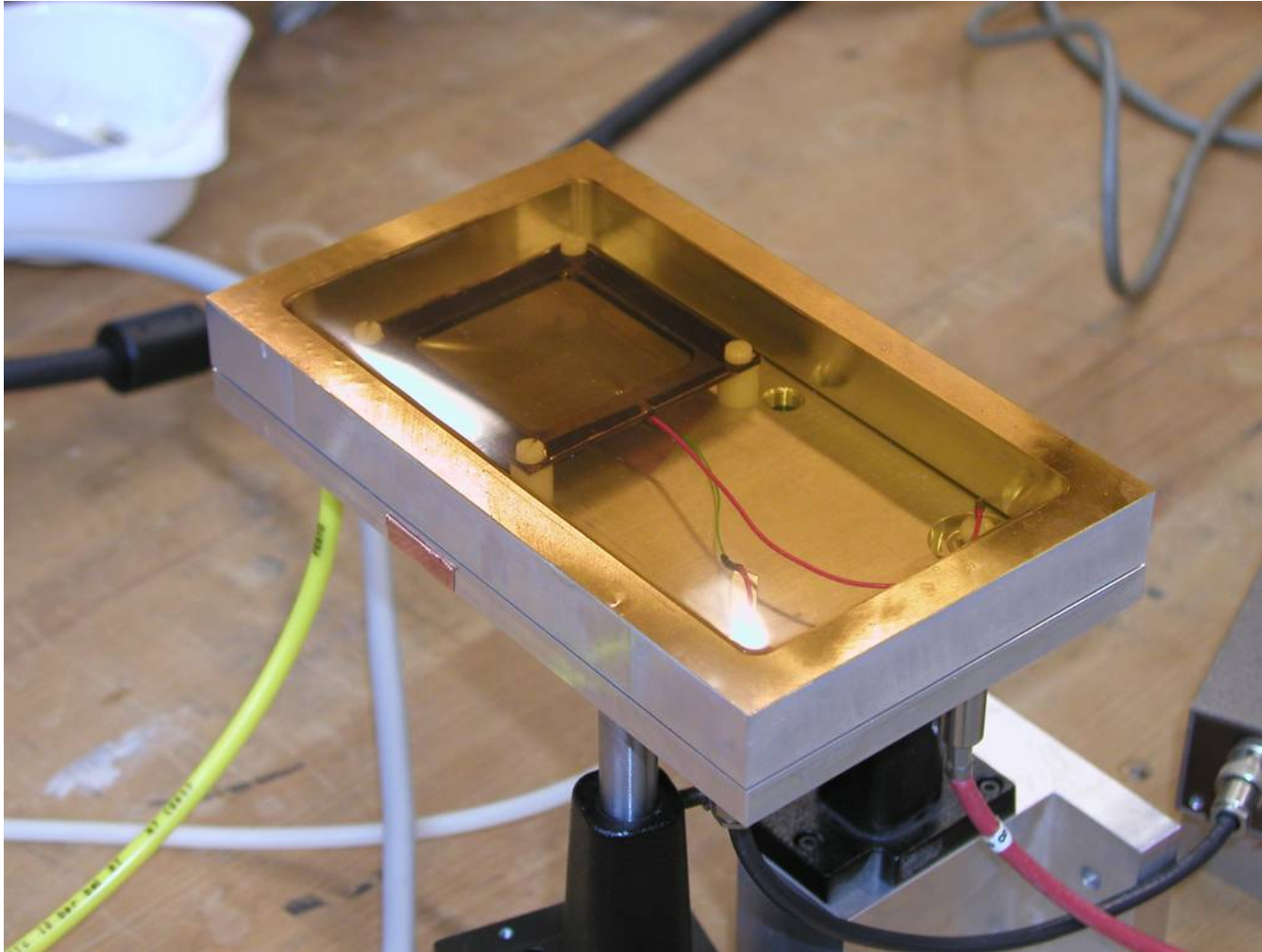


b)

Insulating surface was 75 %
Reduced to 20 %



Micromegas-Medipix2 setup

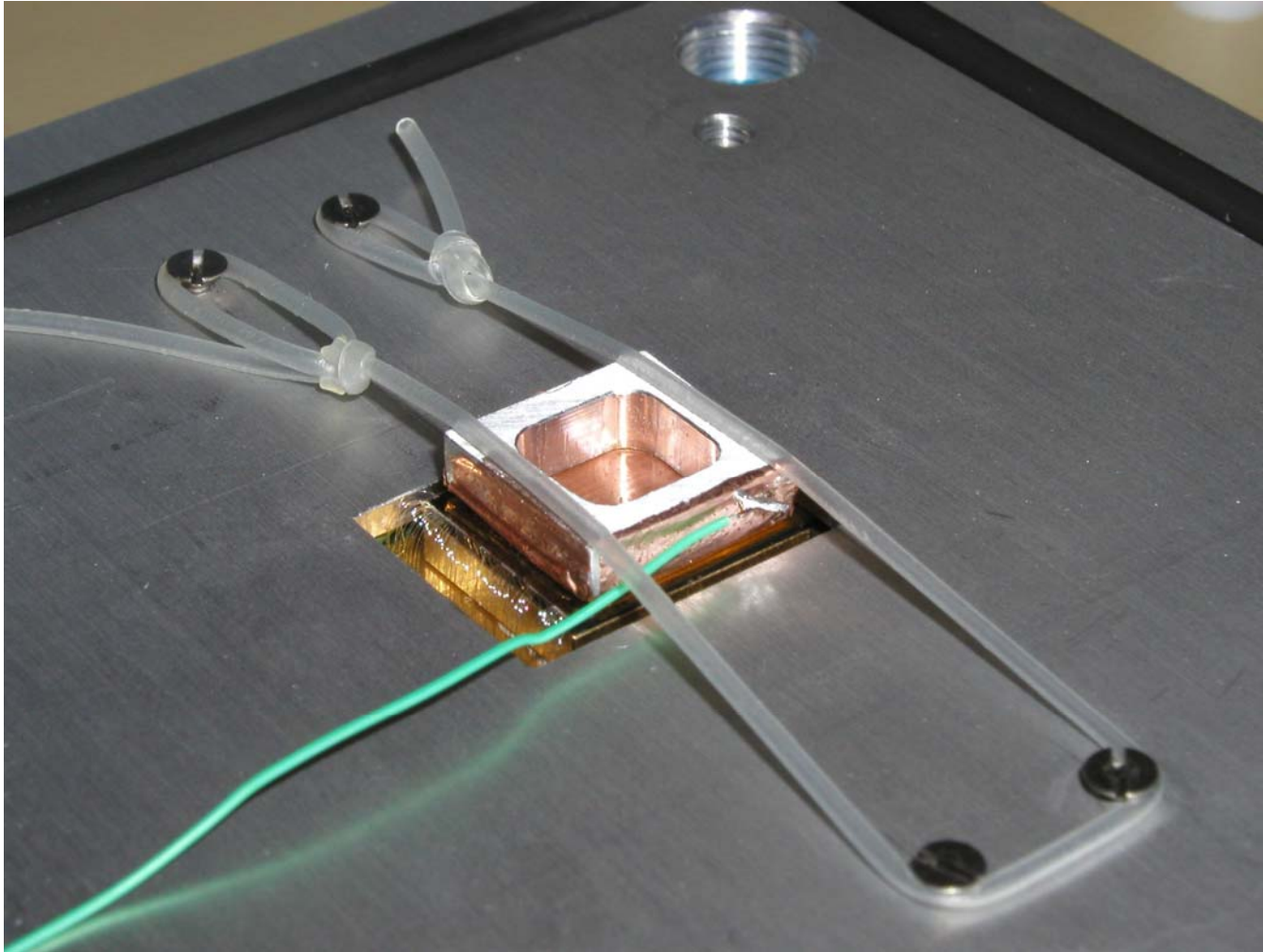


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Chamber Mechanics



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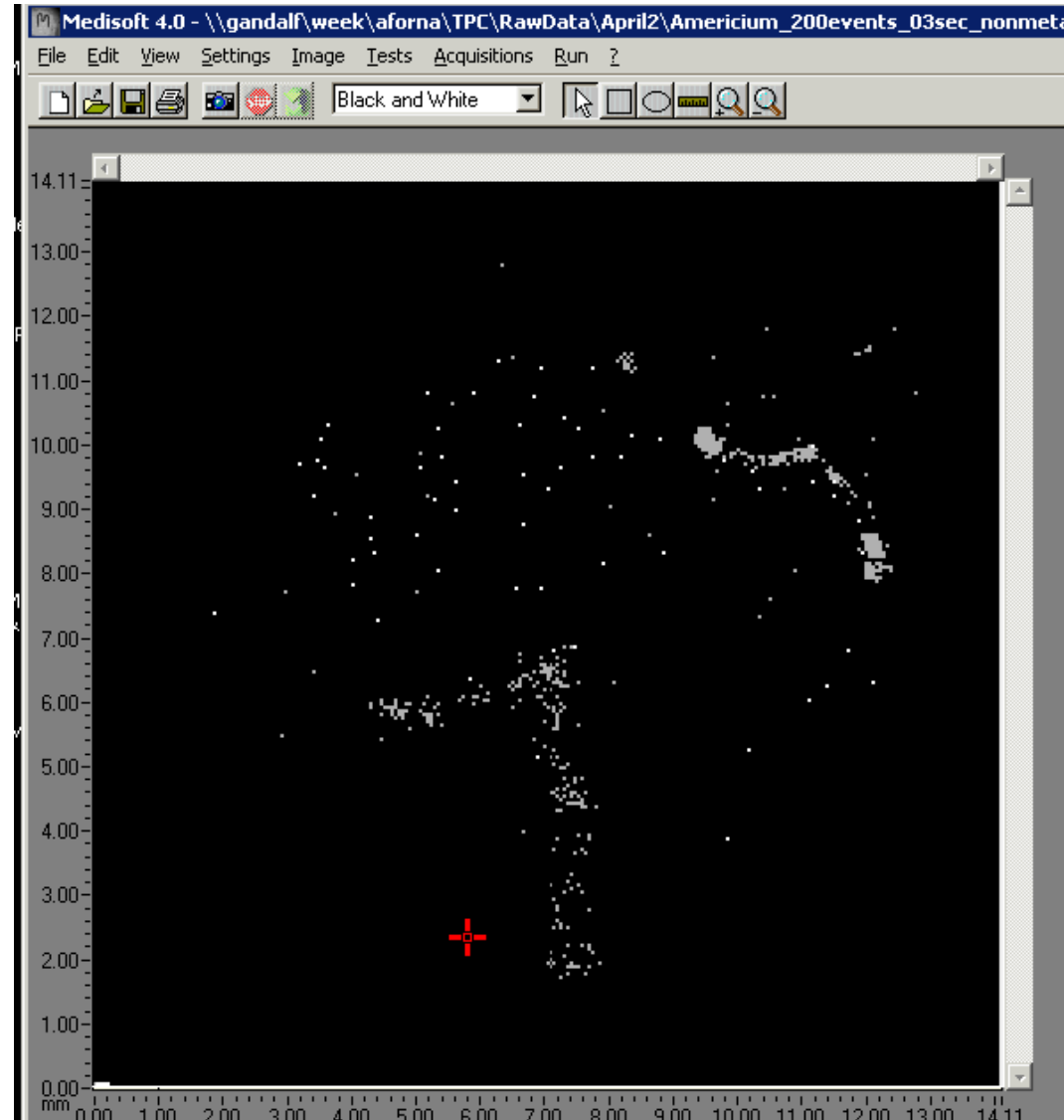
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Radioactive source observation

He/Isobutane
80/20
Non Modified
MediPix

Americium Source



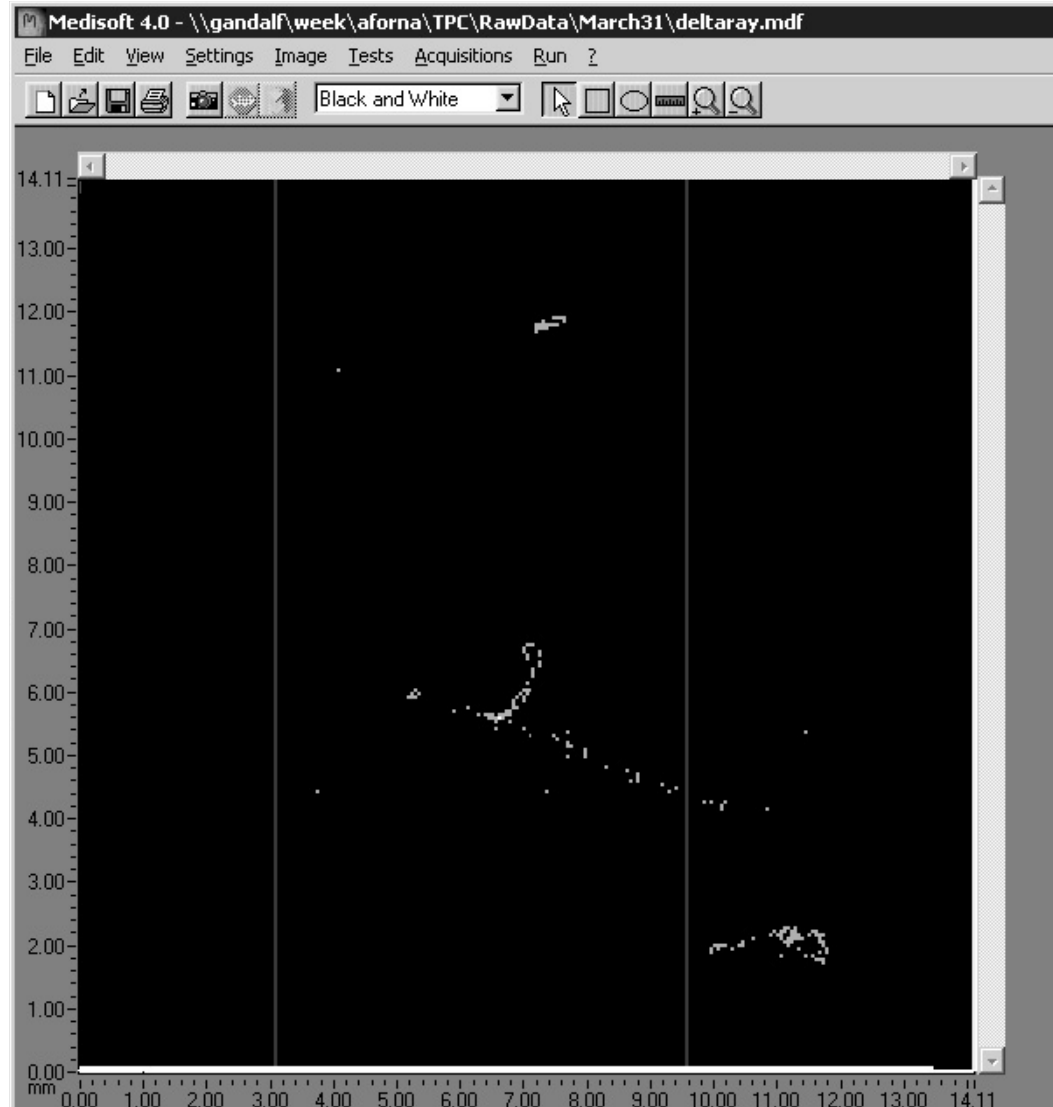
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Cosmic with associated delta ray

He/Isobutane
80/20
Modified MediPix



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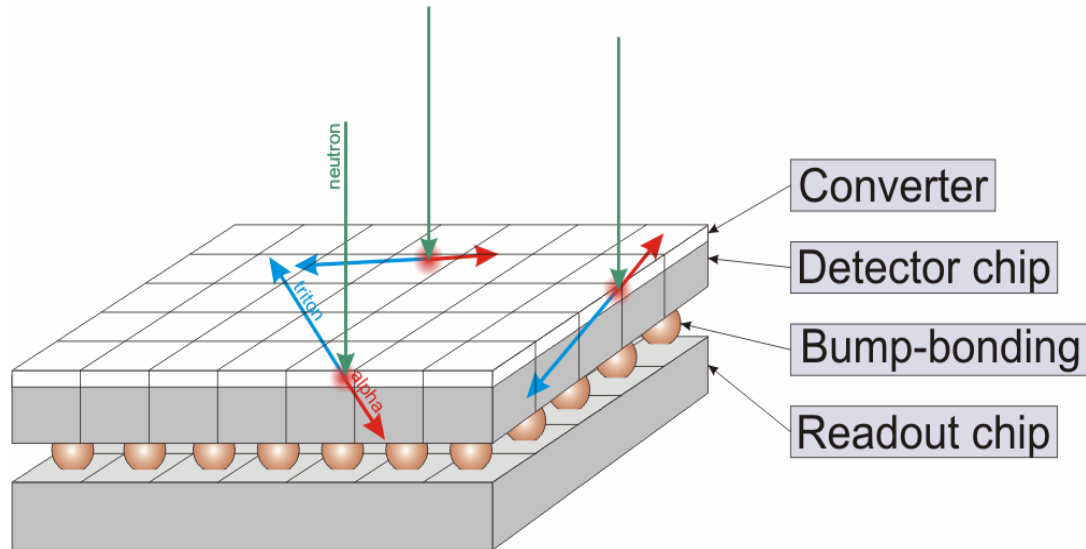
Neutronography with Medipix2

S. Pospisil and co-workers, Czech Technical University, Prague

Conversion of thermal neutrons to heavy charged particles in ${}^6\text{Li}$ converter layer

Reaction: ${}^6\text{Li} + n \rightarrow \alpha (2.05 \text{ MeV}) + {}^3\text{H} (2.72 \text{ MeV})$

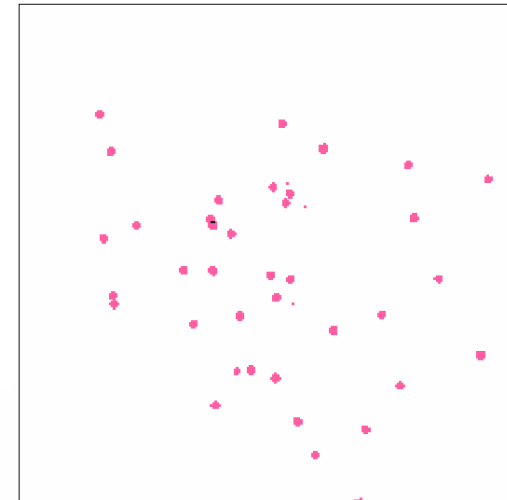
Cross section: 940 barns (0.0253 eV)



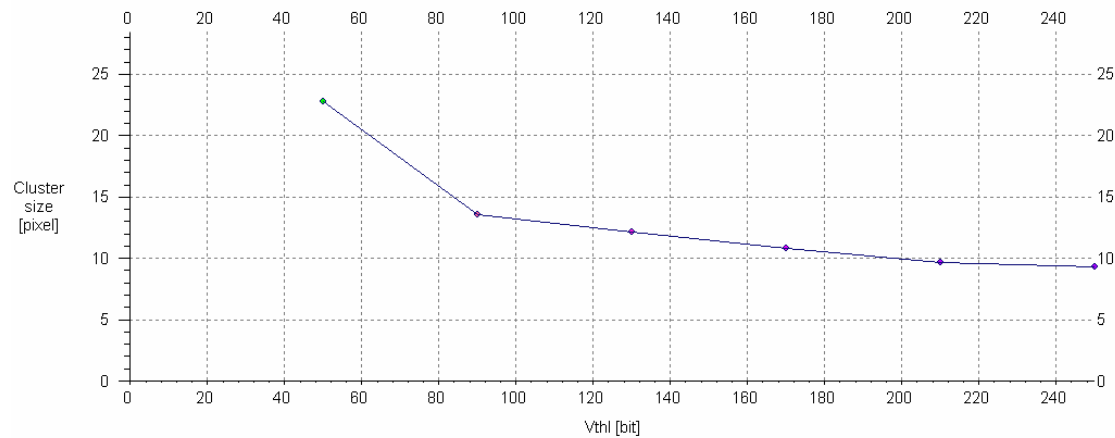


Tests with ^{241}Am alpha source

- Medipix-2 without converter layer
- Energy of alpha particles: 5.6 MeV
- Short exposition time
- Clusters observed



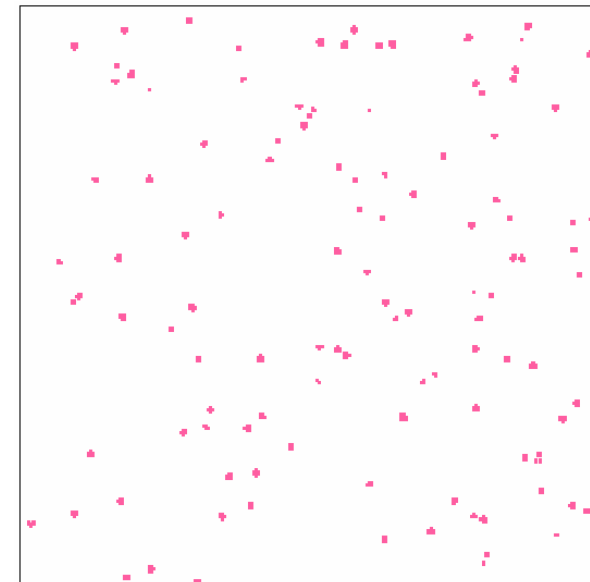
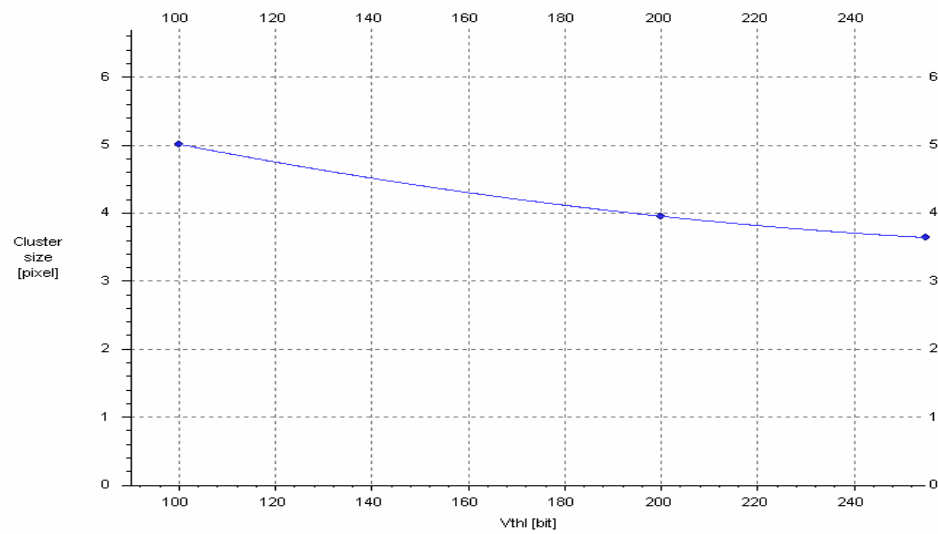
Dependence of average cluster size on threshold





Clusters observed with neutron beam

Dependence of average cluster size on threshold

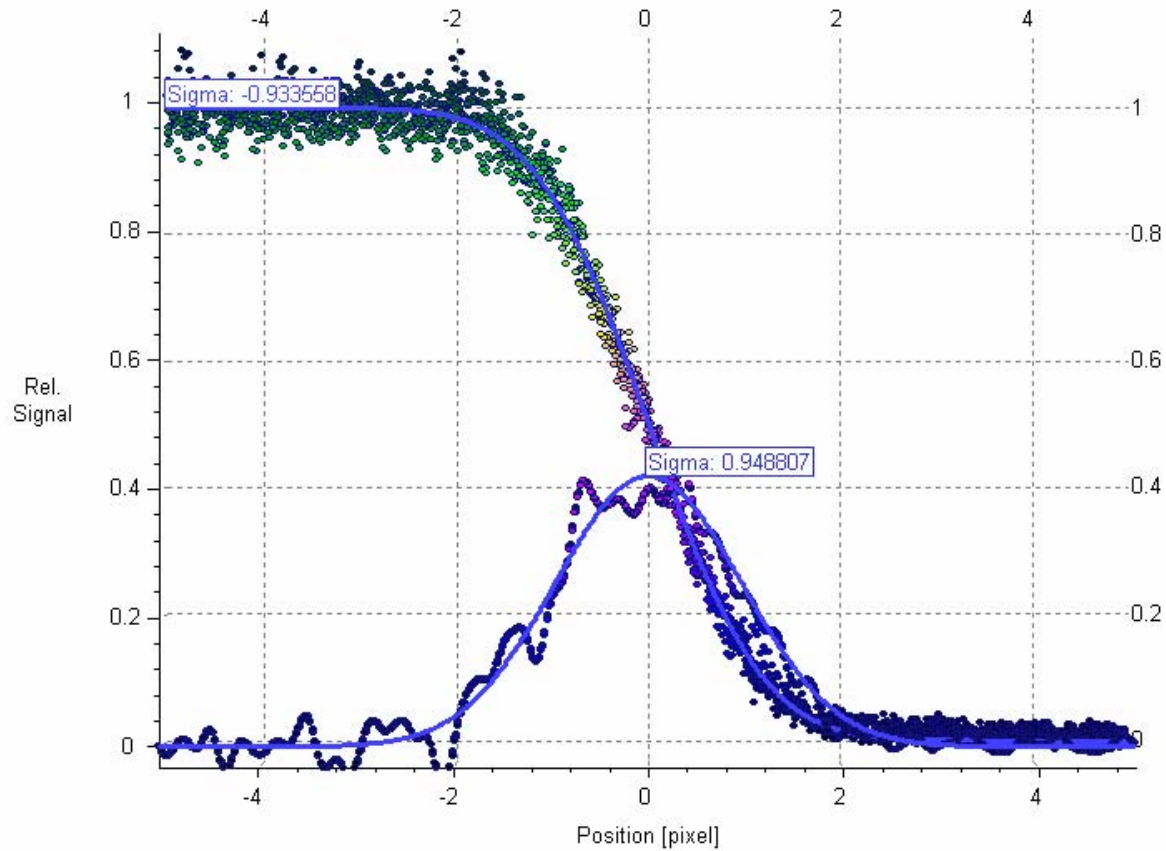


Exposition time = 1 ms

Vfbk=120



Spatial resolution – edge response



22 June 2004

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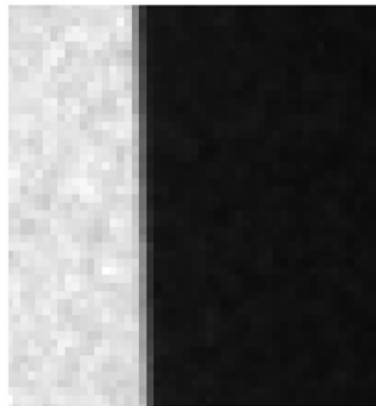


Comparison of Medipix-2 and other neutron imaging detectors

The following tests of Medipix-2 neutron device were done on NEUTRA facility (PSI, Switzerland) in co-operation with E. Lehmann et al. The device was compared to:

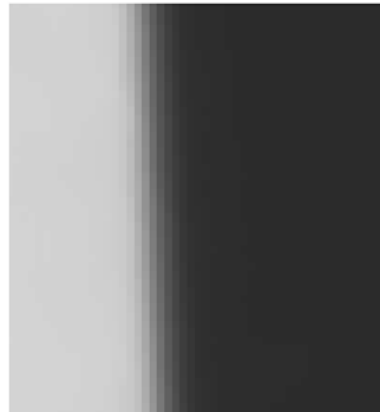
- CCD camera with scintillator mixed with ^6Li (pixel size 0.139 mm)
- Imaging plate (excitation by neutrons, de-excitation by laser scanner followed by light emission, pixel size 50 μm)

Medipix-2



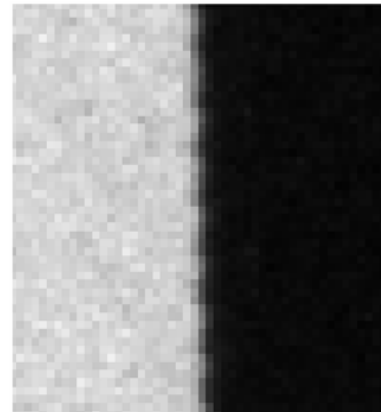
$\sigma=0.83$ pixel
= 46 μm

CCD camera



$\sigma=2.5$ pixel
= 350 μm

Imaging plate



$\sigma=1.06$ pixel
= 53 μm

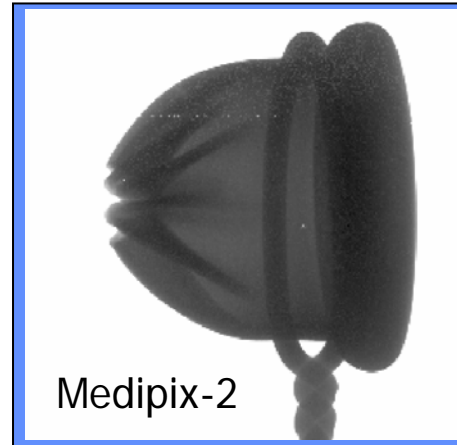


Sample objects – blank cartridge



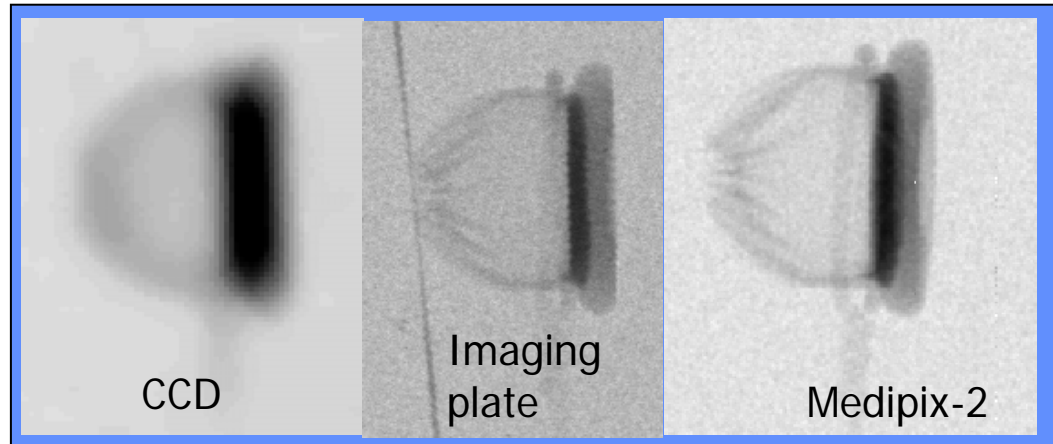
Photograph

Roentgenography



Medipix-2

Neutronography



CCD

Imaging plate

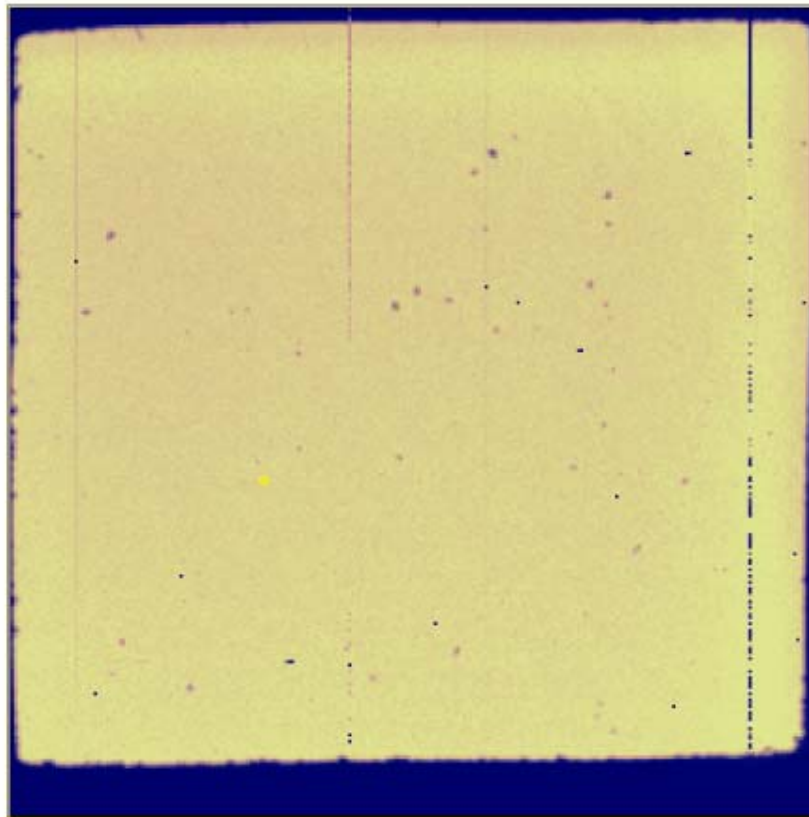
Medipix-2



Medipix2 as an electron detector in a TEM for molecular biology

Flood field image with Si assembly and 150keV electrons

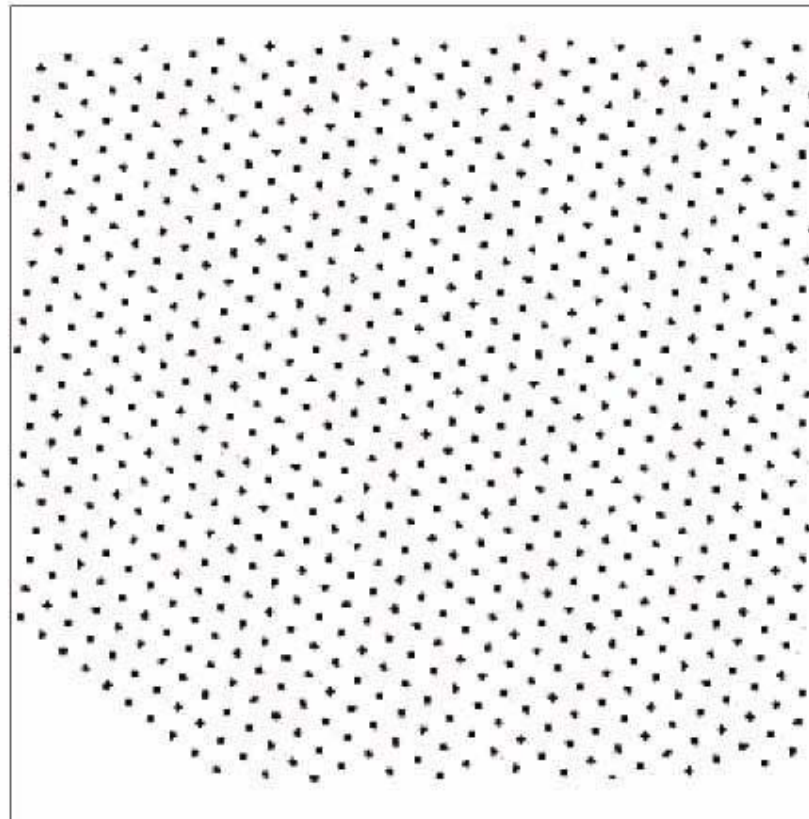
W. Faruqi and co-
workers
Laboratory of
Molecular Biology,
Cambridge





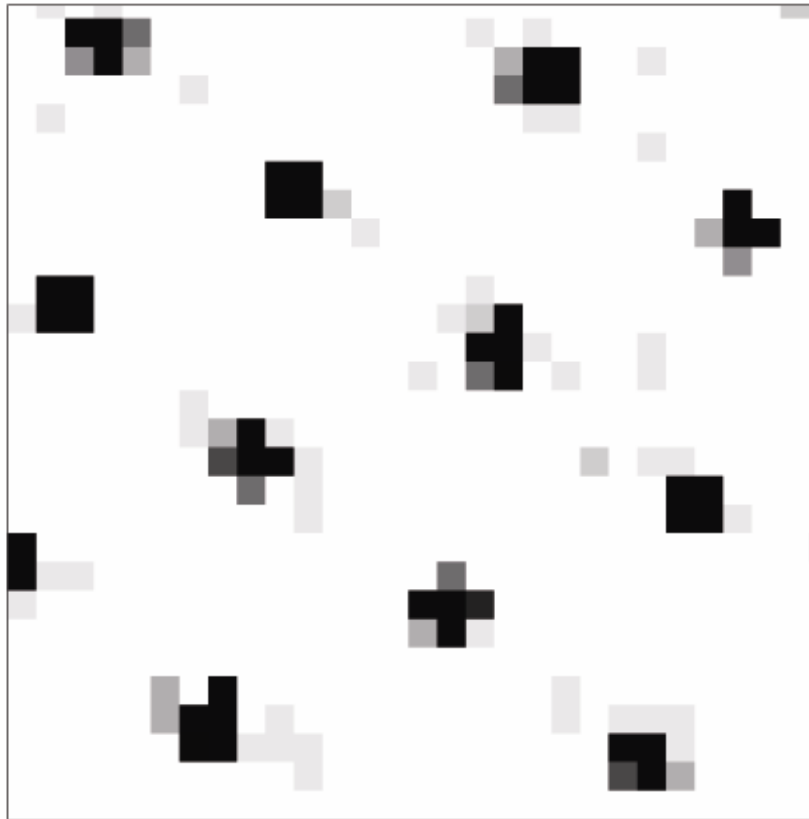
Spot scan

Mean counts 111
 σ counts 11





Spot scan – close up



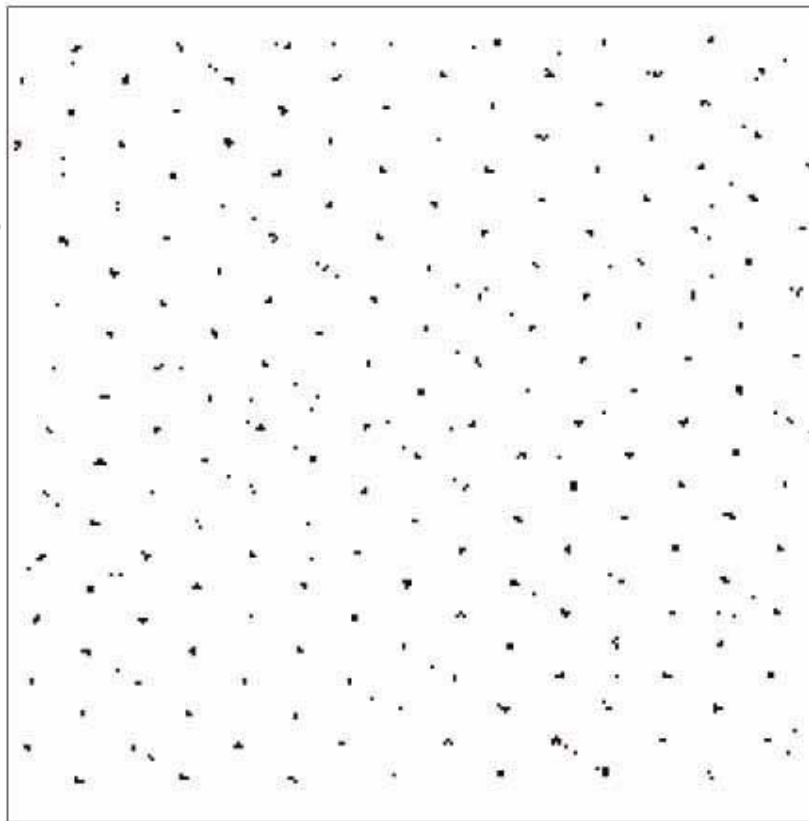
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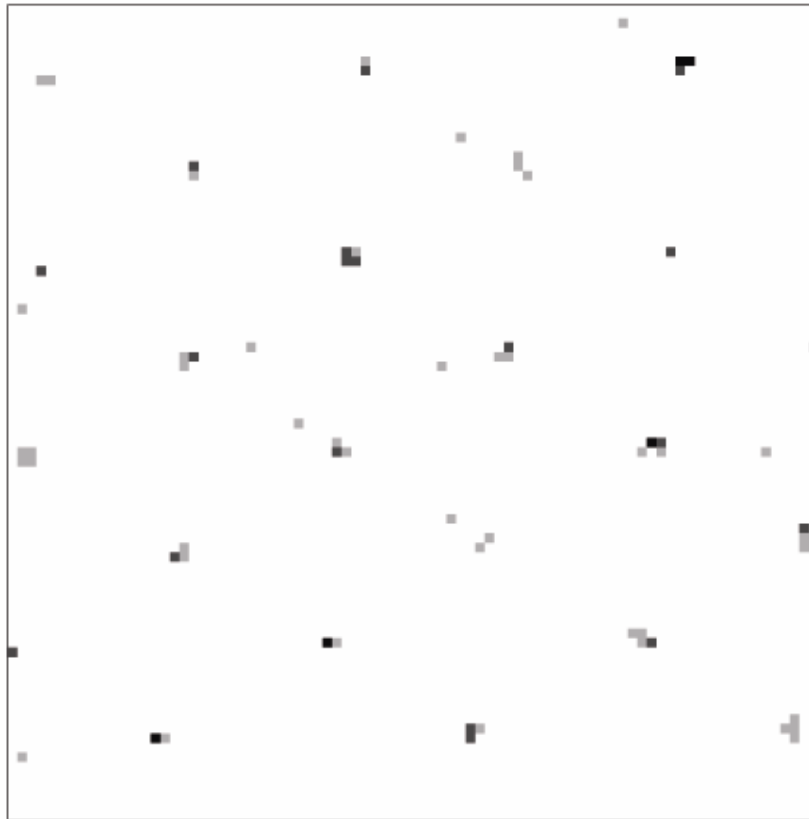
Spot scan

Mean counts 4.7
 σ counts 1.8





Spot scan – close up



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Comparison with film

Spotscan1

	mean	σ
Medipix2	111	11
Film	116	24

Spotscan7

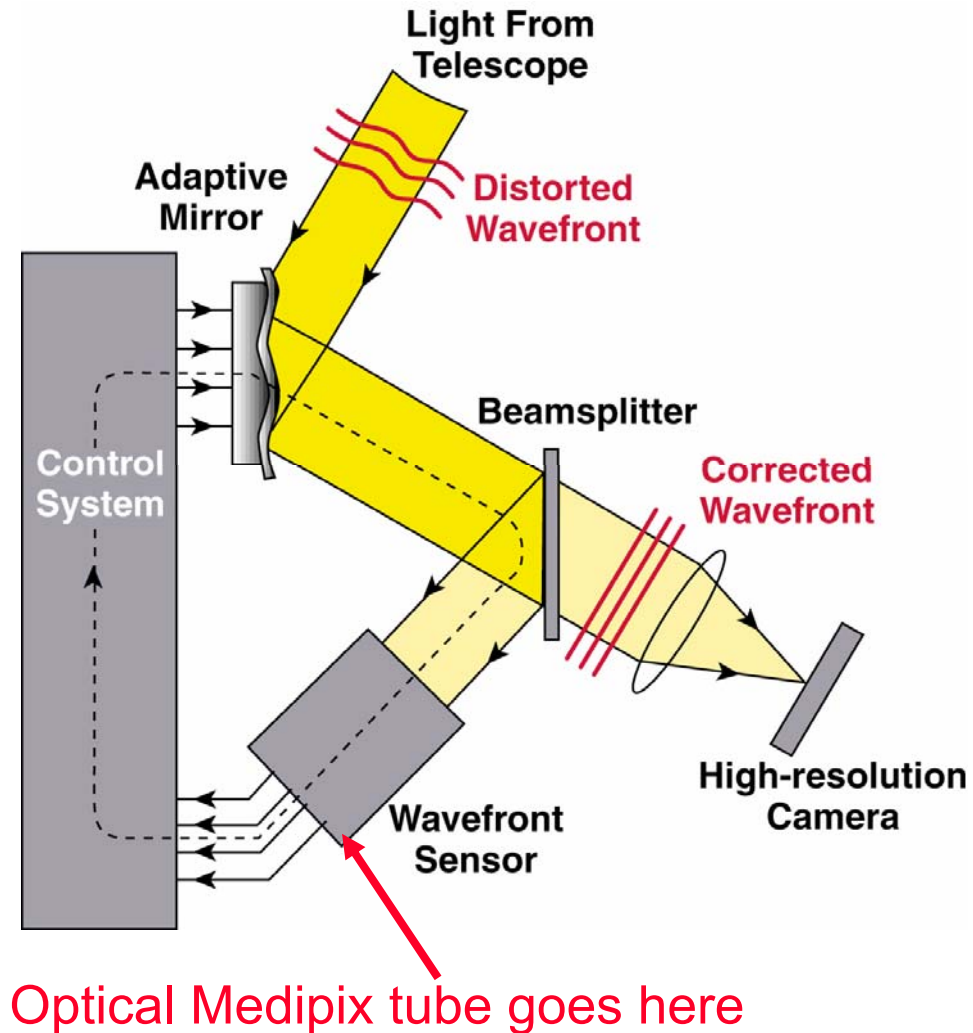
Medipix2	4.7	1.8
Film	spots invisible	



Schematic of adaptive optics system

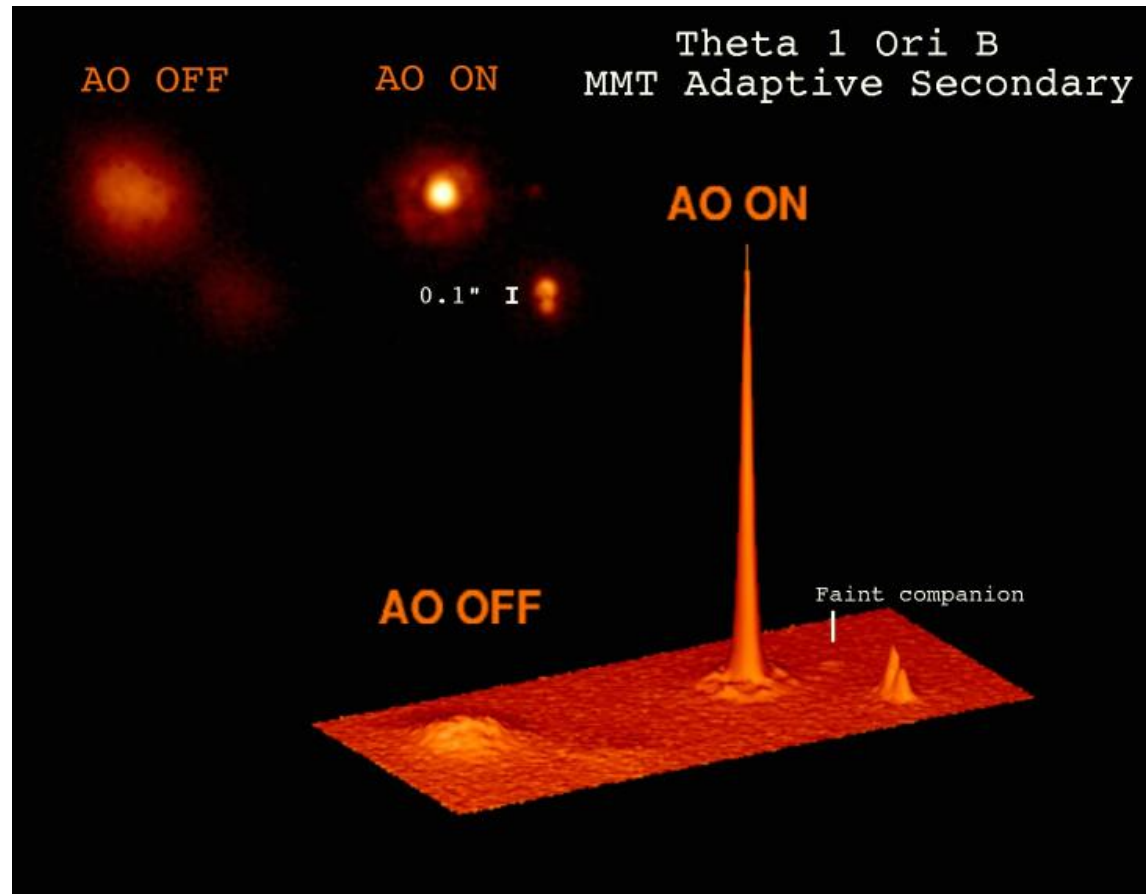
J. Vallergera and coworkers
UC Berkeley
B. Mikulec
Univ. Geneva

Feedback loop:
next cycle
corrects the
(small) errors
of the last cycle





Example for the improvements using AO





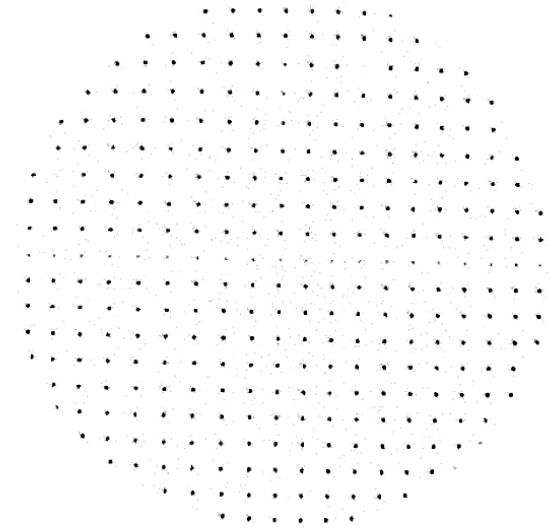
Wavefront Sensors

- ◆ **Future large telescopes need > 5000 actuators**
 - (70 x 70 spot centroids to measure wavefront)
- ◆ **Kilohertz feedback rates (atmospheric timescale)**
- ◆ **1000 detected events per spot for sub-pixel centroiding**

5000 x 1000 x 1000 =

➤ **5 Gigahertz counting rate!**

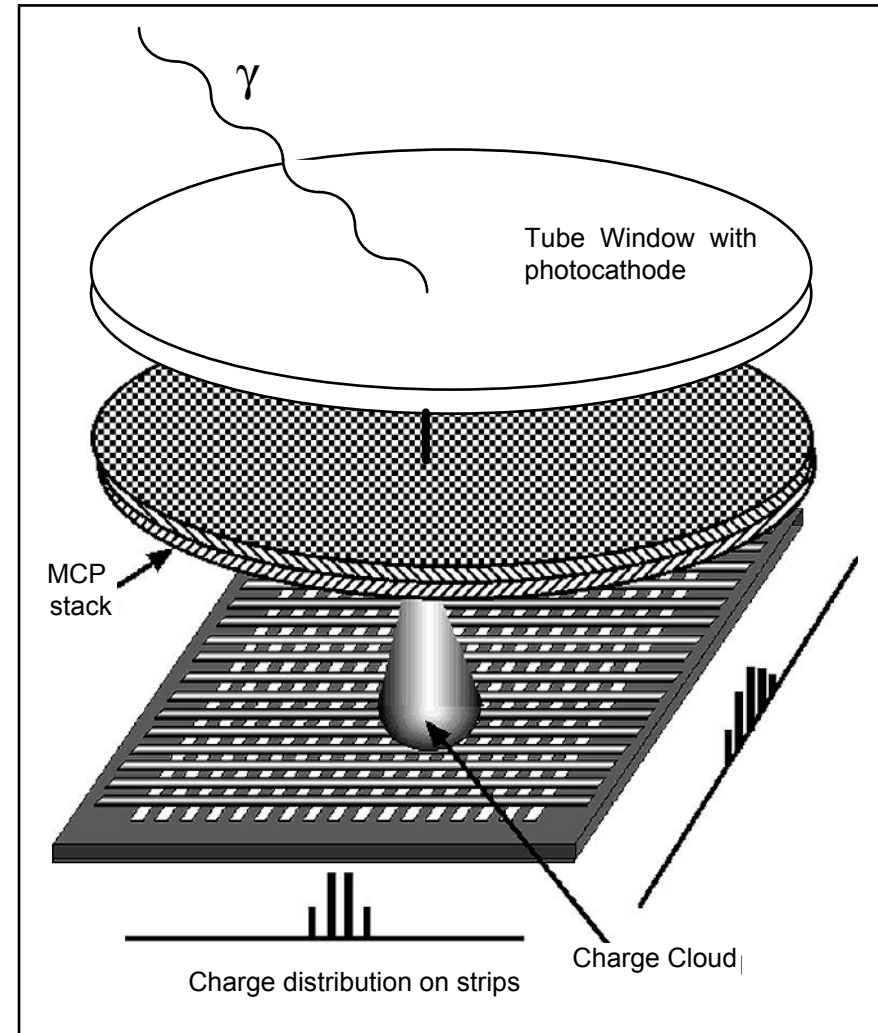
- ◆ **Requires detector integrating several events in time**





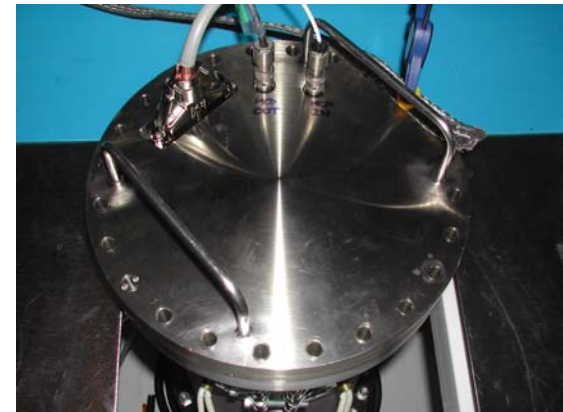
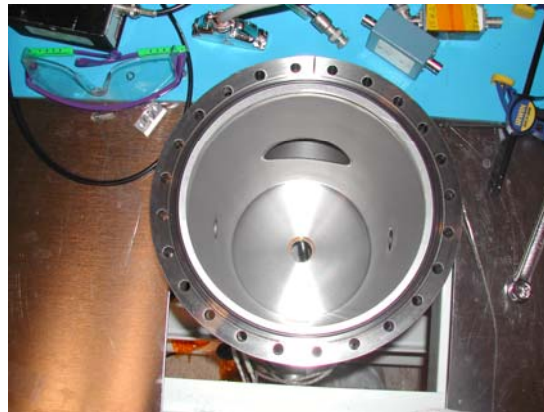
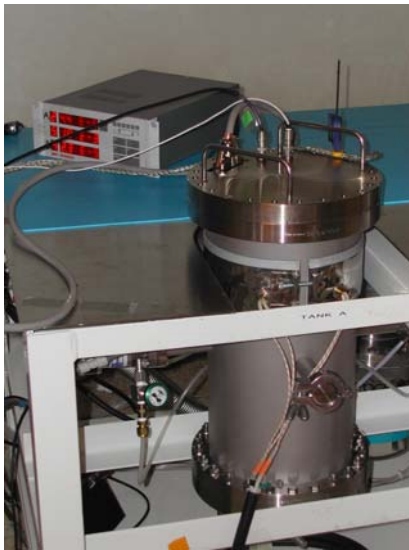
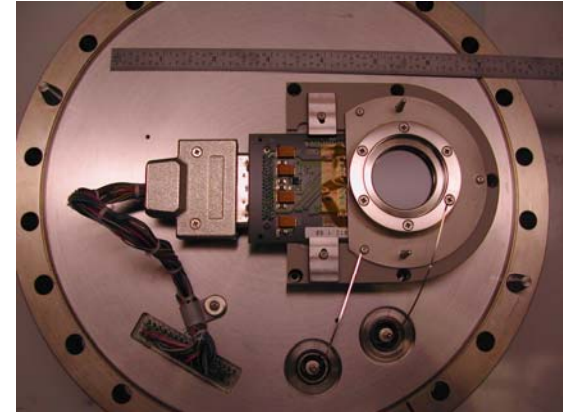
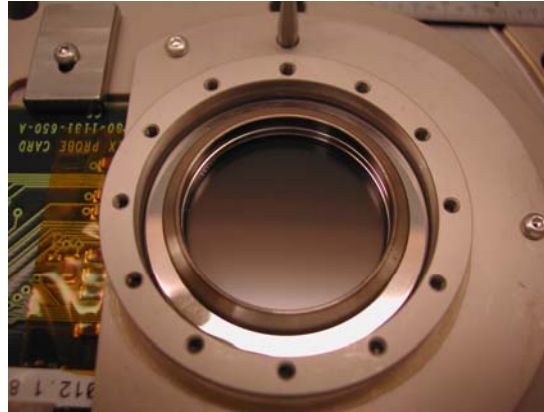
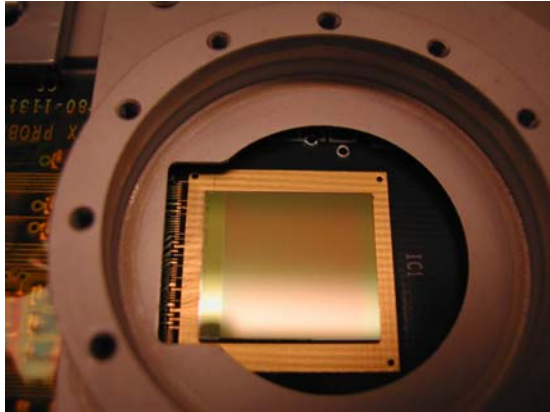
Imaging, Photon Counting Detectors

- ◆ Detects individual quanta of light via photoelectric effect
- ◆ Signal per photon \gg noise
- ◆ Imaging gives X,Y of every event
- ◆ Time of every event also available
- ◆ Maximum ct. rate \sim 2 MHz





The Setup at SSL - Photos



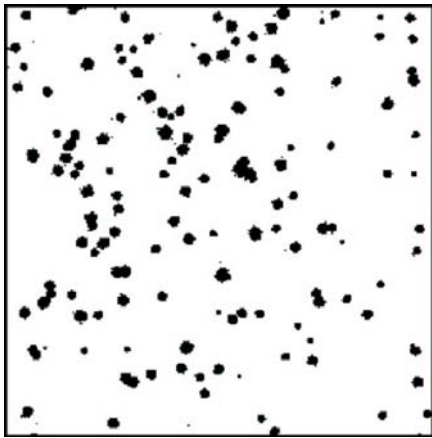
22 June 2004

Michael Campbell



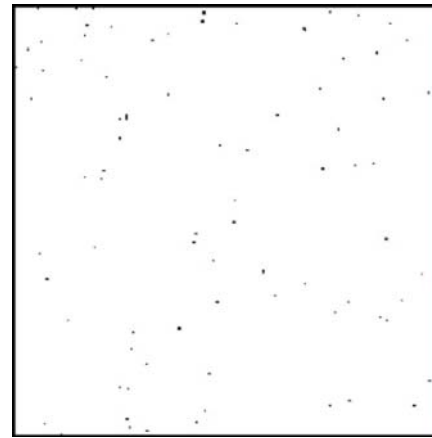
Investigating the Parameters...

- ◆ **Spot area [no. of pixels] is a function of**
 - **MCP gain** (voltage across MCPs):
decreases with **decreasing gain** (threshold effect)
 - **Rear field** (voltage between MCP exit and Medipix chip):
decreases with **increasing rear field**



gain 10^6 , rear field 427 V

single photon
events



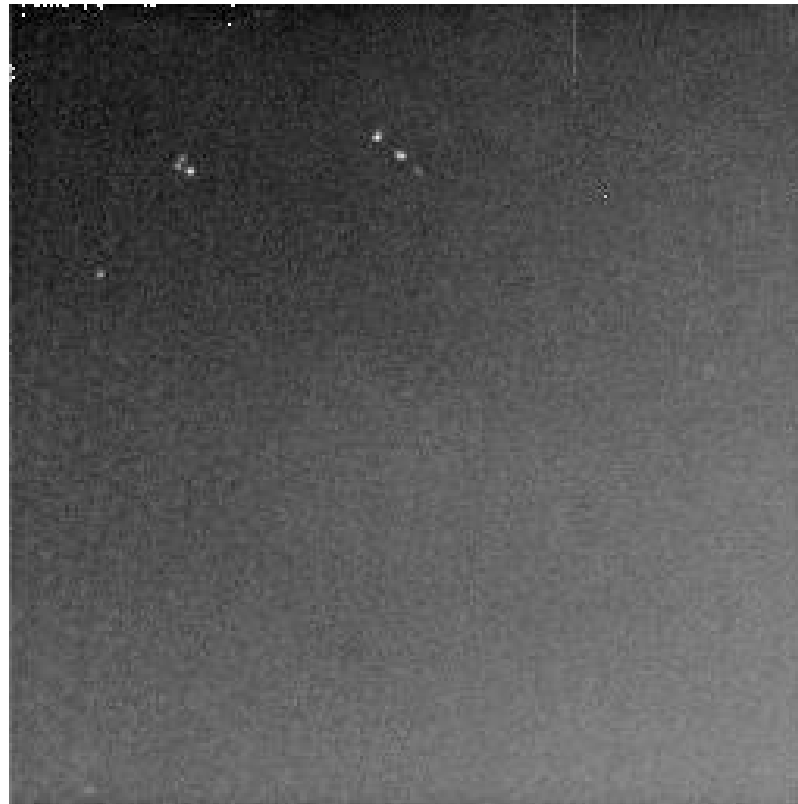
gain 50k, rear field 980 V

- ◆ **Increasing $V_{TH_{low}}$ over the available range (no ext. DAC used) at MCP gain of $\sim 200k$ results in a decreasing spot area size, but the number of spots stays approximately constant.**



Flat Field Image

- ◆ Take image at 50ke gain and 1600 V rear field (~5000 counts/pixel). Average single spot area: 2.4 pixels





Limitations of Medipix2 system

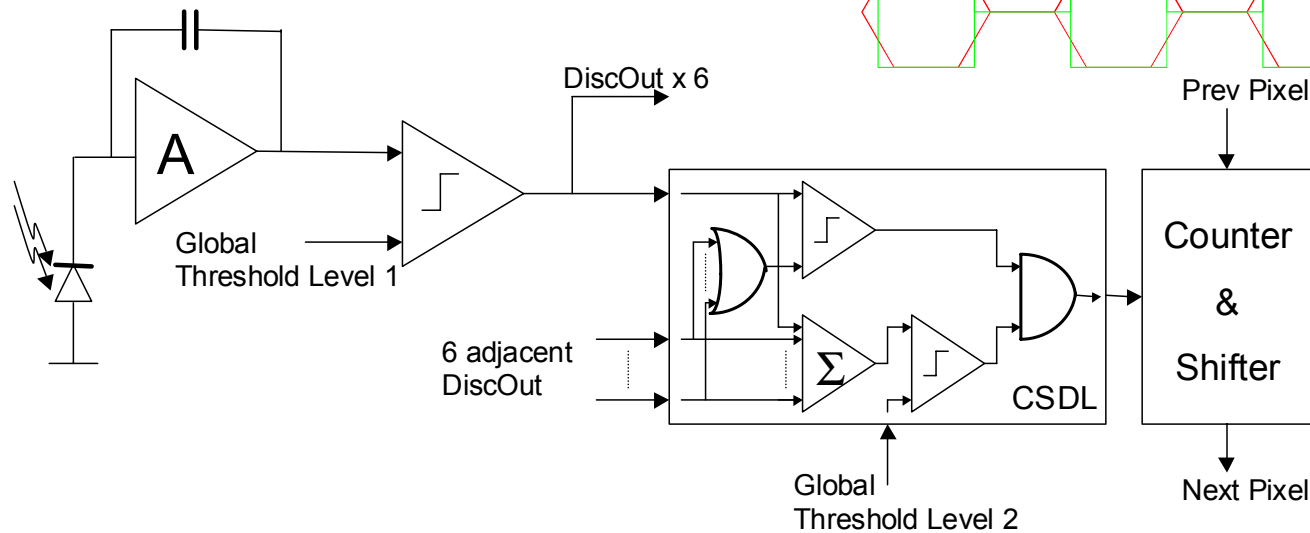
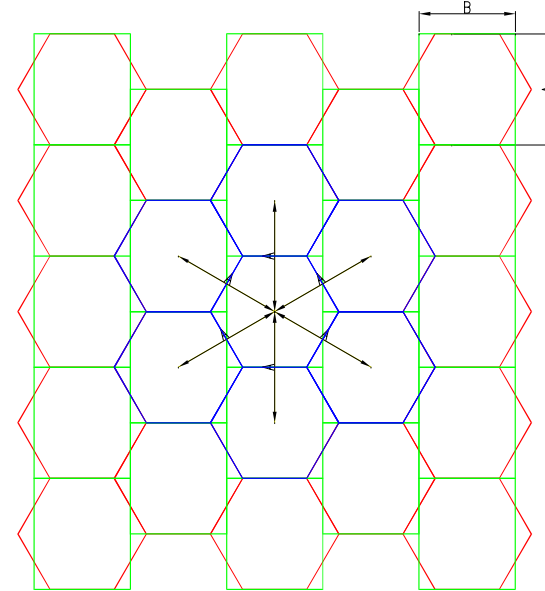
- ◆ **Counting only hits in one energy window**
- ◆ **Charge sharing between pixels leads to low energy tail**
- ◆ **Tiling only possible on 3 sides**

- ◆ **Solutions exist for these but a new chip design would be required**



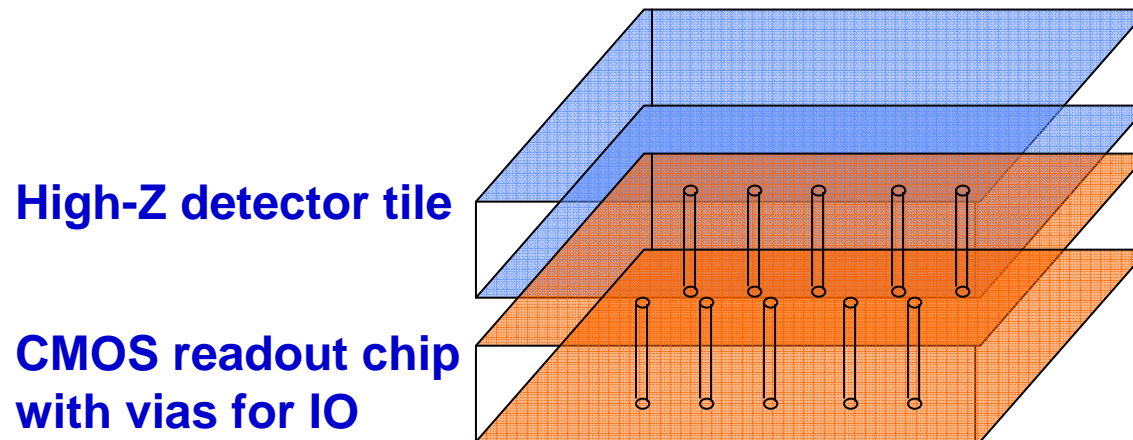
Charge sharing – possible solution

- ◆ **sensor pixels: hexagons \Rightarrow 6 neighbours**
- ◆ **electronic pixels: rectangular**
 - 2 different threshold levels
 - longest pulse \Rightarrow biggest share of charge
 - sum of 7 pixels is compared to second threshold





Tiling- possible solution





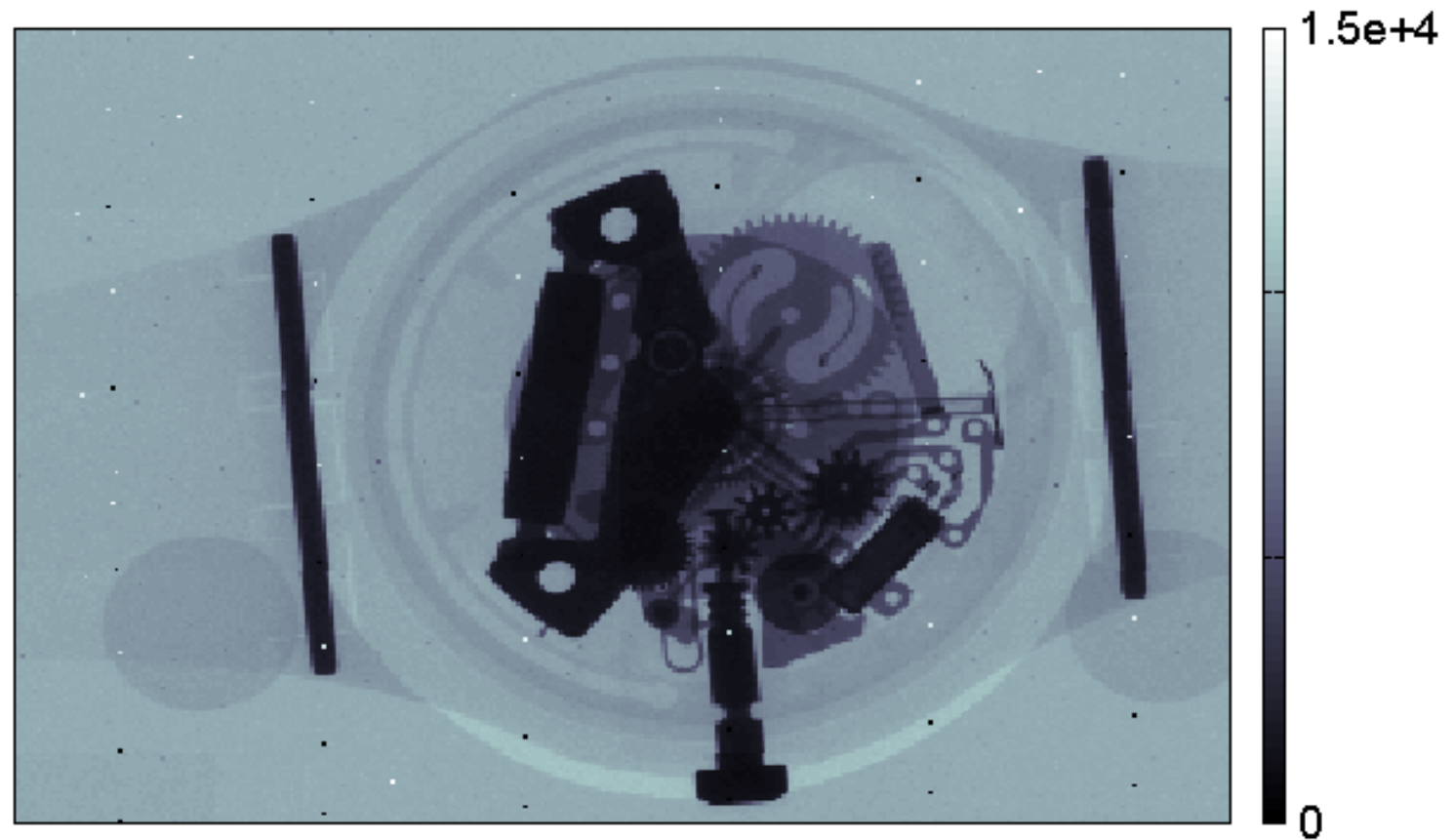
Concluding remarks

- ◆ **Medipix2 is a successful spin off project based heavily on developments for HEP. Application fields (foreseen and otherwise) include:**
 - Medical x-ray imaging and tomography
 - X-ray imaging for material science
 - Synchrotrons light imaging
 - Neutron imaging
 - TEM for biological structural analysis
 - Fast visible photon imaging (when combined with MCP)
- ◆ **Access to modern CMOS technology and to sophisticated design tools is a key this kind of project**
- ◆ **High prototyping costs led to the formation of a large collaboration of scientific institutes**
- ◆ **As well as being a low cost beacon activity for HEP the enthusiasm and activity generated by such developments spins back into detector development for HEP (Gas detector readout and fast visible light detection)**

...and lastly...



Its fun!



Thanks to R. Ballabriga, E. Heijne, X. Llopart and L. Tlustos

22 June 2004

Michael Campbell